NEC

MOS INTEGRATED CIRCUIT
μPD42S16400, 4216400, 42S17400, 4217400

16 M-BIT DYNAMIC RAM
4 M-WORD BY 4-BIT, FAST PAGE MODE

DESCRIPTION

The μPD42S16400, 4216400, 42S17400, 4217400 are 4 194 304 words by 4 bits dynamic CMOS RAMs.

These differ in refresh cycle and the μPD42S16400, 42S17400 can execute $\overline{CAS}$ before $\overline{RAS}$ self refresh and have various packages (see the table below).

FEATURES

- 4 194 304 words by 4 bits organization
- Single +5.0 V±10 % power supply
- Fast page mode
- The μPD42S16400, 42S17400 can execute $\overline{CAS}$ before $\overline{RAS}$ self refresh.

Part number	Refresh cycle	Refresh	Power consumption at standby (MAX.)
μPD42S16400	4 096 cycles/128 ms	$\overline{CAS}$ before $\overline{RAS}$ self refresh, $\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh	1.4 mW (CMOS level input)
μPD42S17400	2 048 cycles/128 ms		
μPD4216400	4 096 cycles/64 ms	$\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh	5.5 mW (CMOS level input)
μPD4217400	2 048 cycles/32 ms		

★ ★

- Fast access and cycle time

Part number	Power consumption Active (MAX.)	Access time (MAX.)	R/W cycle time (MIN.)	Fast page mode cycle time (MIN.)
μPD42S16400-50, 4216400-50	550 mW	50 ns	90 ns	35 ns
μPD42S17400-50, 4217400-50	660 mW			
μPD42S16400-60, 4216400-60	495 mW	60 ns	110 ns	40 ns
μPD42S17400-60, 4217400-60	605 mW			
μPD42S16400-70, 4216400-70	440 mW	70 ns	130 ns	45 ns
μPD42S17400-70, 4217400-70	550 mW			
μPD42S16400-80, 4216400-80	385 mW	80 ns	150 ns	50 ns
μPD42S17400-80, 4217400-80	495 mW			

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- Various packages

Part number	Package
μPD42S16400, 42S17400	26-pin plastic TSOP (300 mil), 26-pin plastic SOJ (300 mil)
μPD4216400, 4217400	26-pin plastic TSOP (300 mil), 28-pin plastic TSOP (400 mil) 26-pin plastic SOJ (300 mil), 28-pin plastic SOJ (400 mil) 24-pin plastic ZIP (475 mil)

The information in this document is subject to change without notice.

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The mark ★ shows revised points.

ORDERING INFORMATION

(1/3)

Part number	Access time (MAX.)	Package	Refresh
μPD42S16400G3-50	50 ns	26-pin plastic TSOP (II) (300 mil) Normal pinout	$\overline{CAS}$ before $\overline{RAS}$ self refresh $\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD42S17400G3-50			
μPD42S16400G3-60	60 ns		
μPD42S17400G3-60			
μPD42S16400G3-70	70 ns		
μPD42S17400G3-70			
μPD42S16400G3-80	80 ns		
μPD42S17400G3-80			
μPD42S16400G3M-50	50 ns	26-pin plastic TSOP (II) (300 mil) Reverse pinout	
μPD42S17400G3M-50			
μPD42S16400G3M-60	60 ns		
μPD42S17400G3M-60			
μPD42S16400G3M-70	70 ns		
μPD42S17400G3M-70			
μPD42S16400G3M-80	80 ns		
μPD42S17400G3M-80			
μPD42S16400LA-50	50 ns	26-pin plastic SOJ (300 mil)	
μPD42S17400LA-50			
μPD42S16400LA-60	60 ns		
μPD42S17400LA-60			
μPD42S16400LA-70	70 ns		
μPD42S17400LA-70			
μPD42S16400LA-80	80 ns		
μPD42S17400LA-80			

(2/3)

Part number	Access time (MAX.)	Package	Refresh
μPD4216400G3-50	50 ns	26-pin plastic TSOP (II) (300 mil) Normal pinout	$\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD4217400G3-50			
μPD4216400G3-60	60 ns		
μPD4217400G3-60			
μPD4216400G3-70	70 ns		
μPD4217400G3-70			
μPD4216400G3-80	80 ns		
μPD4217400G3-80			
μPD4216400G3M-50	50 ns	26-pin plastic TSOP (II) (300 mil) Reverse pinout	
μPD4217400G3M-50			
μPD4216400G3M-60	60 ns		
μPD4217400G3M-60			
μPD4216400G3M-70	70 ns		
μPD4217400G3M-70			
μPD4216400G3M-80	80 ns		
μPD4217400G3M-80			
μPD4216400G5-60	60 ns	28-pin plastic TSOP (II) (400 mil) Normal pinout	
μPD4217400G5-60			
μPD4216400G5-70	70 ns		★
μPD4217400G5-70			
μPD4216400G5-80	80 ns		
μPD4217400G5-80			
μPD4216400G5M-60	60 ns	28-pin plastic TSOP (II) (400 mil) Reverse pinout	
μPD4217400G5M-60			★
μPD4216400G5M-70	70 ns		
μPD4217400G5M-70			
μPD4216400G5M-80	80 ns		
μPD4217400G5M-80			

Part number	Access time (MAX.)	Package	Refresh
μPD4216400LA-50	50 ns	26-pin plastic SOJ (300 mil)	$\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD4217400LA-50			
μPD4216400LA-60	60 ns		
μPD4217400LA-60			
μPD4216400LA-70	70 ns		
μPD4217400LA-70			
μPD4216400LA-80	80 ns		
μPD4217400LA-80			
μPD4216400LE-60	60 ns	28-pin plastic SOJ (400 mil)	
μPD4217400LE-60			
★ μPD4216400LE-70	70 ns		
μPD4217400LE-70			
μPD4216400LE-80	80 ns		
μPD4217400LE-80			
μPD4216400V-60	60 ns	24-pin plastic ZIP (475 mil)	
μPD4217400V-60			
★ μPD4216400V-70	70 ns		
μPD4217400V-70			
μPD4216400V-80	80 ns		
μPD4217400V-80			

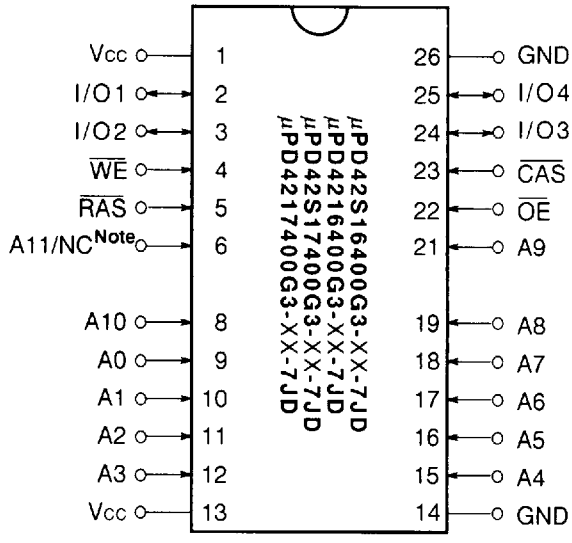
QUALITY GRADE

STANDARD

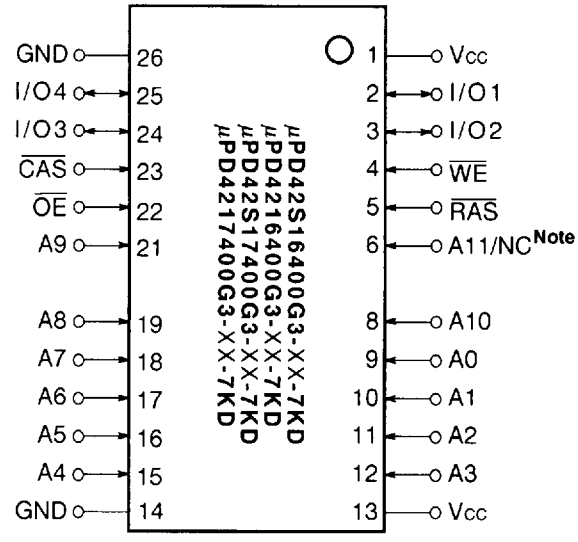
Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

PIN CONFIGURATIONS (Marking Side)

26-pin Plastic TSOP (II) (300 mil)



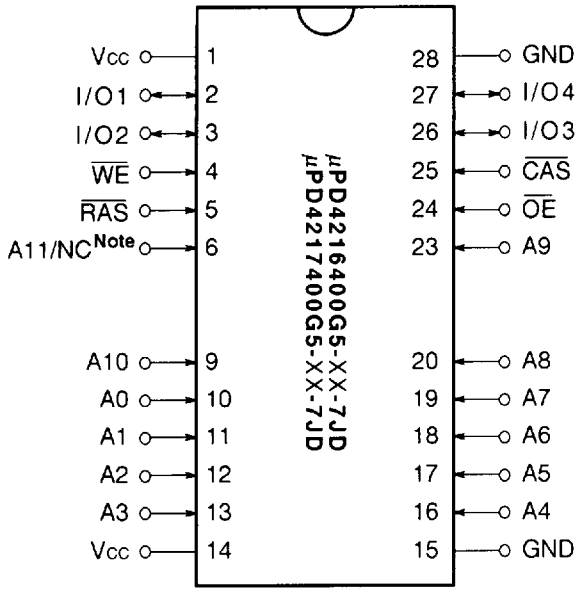
Reverse bent



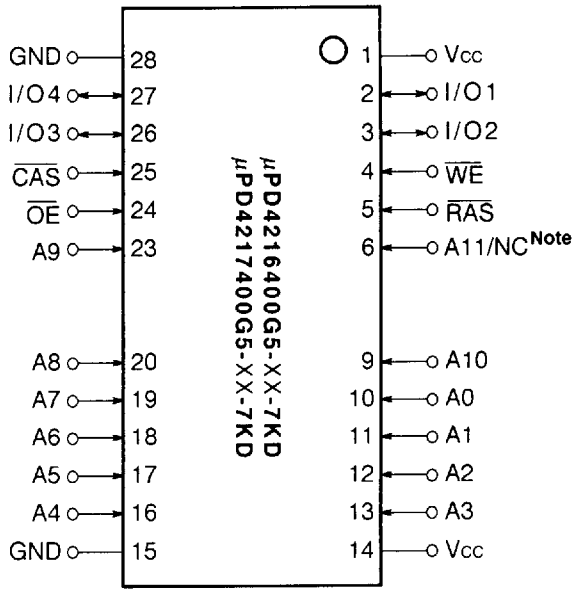
Note A11 ···μPD42S16400, 4216400
NC ···μPD42S17400, 4217400

A0 to A11	: Address Inputs
I/O1 to I/O4	: Data Inputs/Outputs
$\overline{RAS}$	: Row Address Strobe
$\overline{CAS}$	: Column Address Strobe
$\overline{WE}$	: Write Enable
$\overline{OE}$	: Output Enable
Vcc	: Supply Voltage
GND	: Ground
NC	: No Connection

28-pin Plastic TSOP (II) (400 mil)



Reverse bent



Note A11 ···μPD42S16400, 4216400
NC ···μPD42S17400, 4217400

A0 to A11	: Address Inputs
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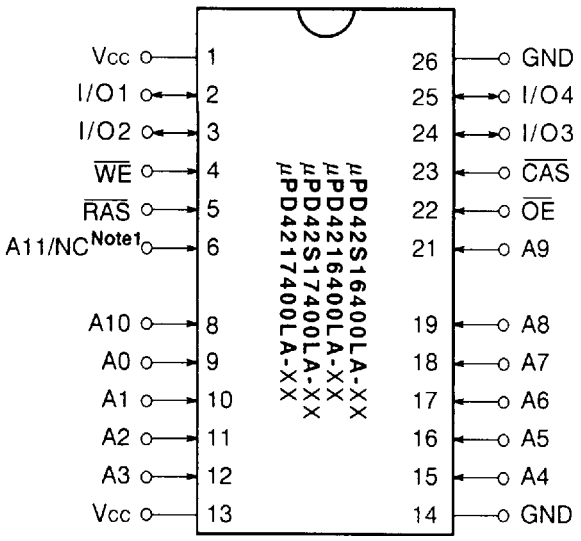
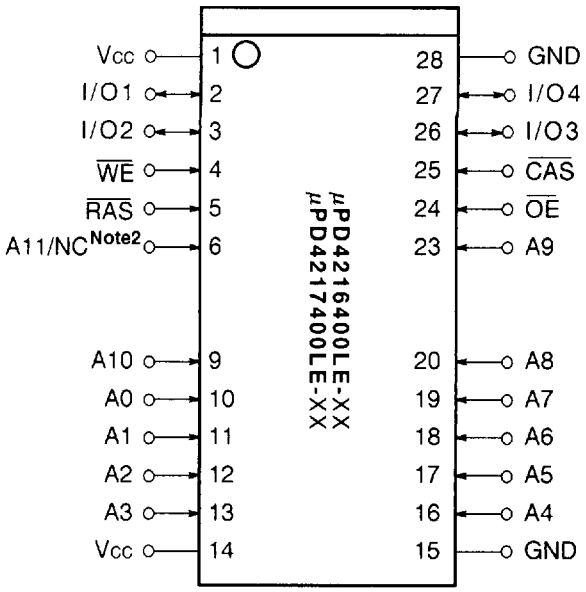
$\overline{RAS}$	: Row Address Strobe
$\overline{CAS}$	: Column Address Strobe
$\overline{WE}$	: Write Enable
$\overline{OE}$	: Output Enable
Vcc	: Supply Voltage
GND	: Ground
NC	: No Connection

26-pin Plastic SOJ (300 mil)



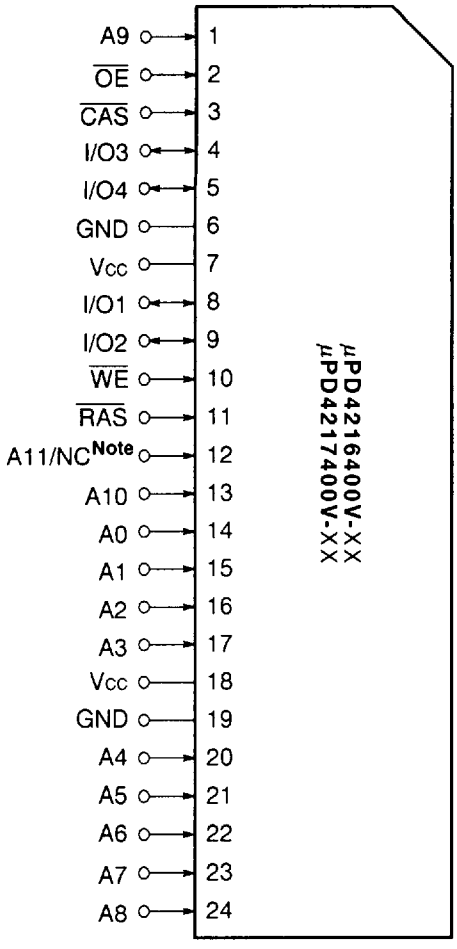
28-pin Plastic SOJ (400 mil)



Notes 1. A11 ··· μPD42S16400, 4216400
NC ··· μPD42S17400, 4217400
2. A11 ··· μPD4216400
NC ··· μPD4217400

A0 to A11	: Address Inputs
I/O1 to I/O4	: Data Inputs/Outputs
$\overline{RAS}$	: Row Address Strobe
$\overline{CAS}$	: Column Address Strobe
$\overline{WE}$	: Write Enable
$\overline{OE}$	: Output Enable
Vcc	: Supply Voltage
GND	: Ground
NC	: No Connection

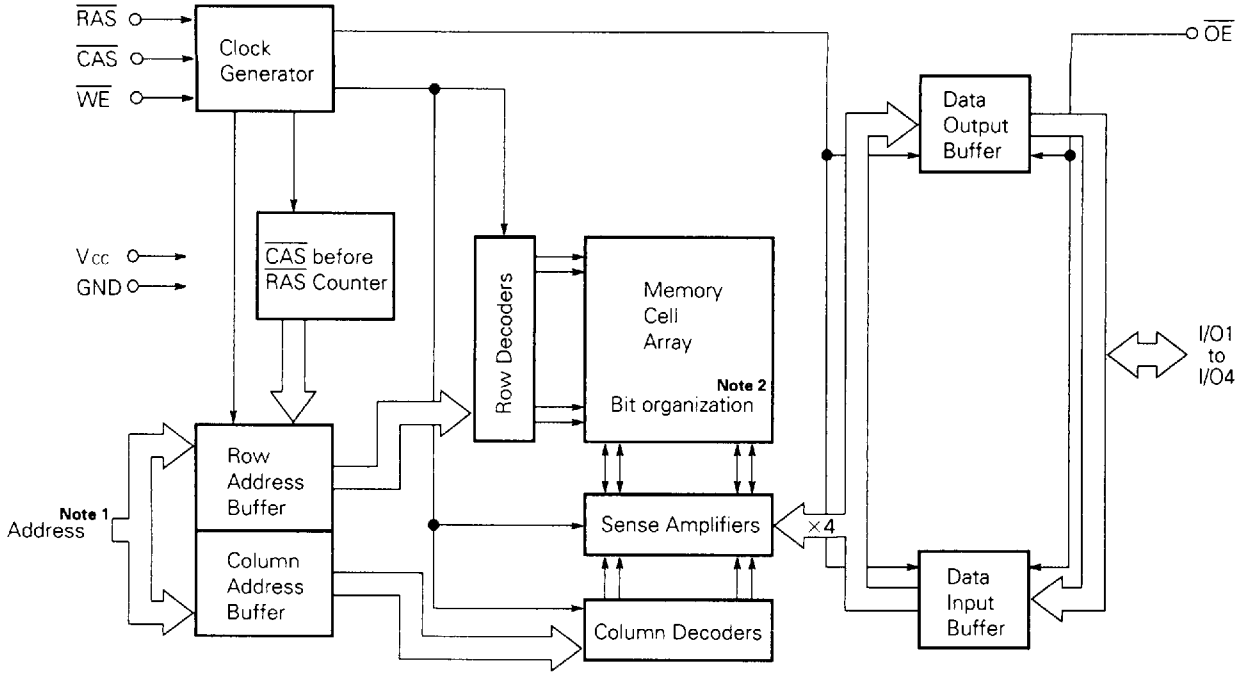
24-pin Plastic ZIP (475 mil)



Note A11 ··· μPD4216400
NC ··· μPD4217400

A0 to A11	: Address Inputs
I/O1 to I/O4	: Data Inputs/Outputs
$\overline{RAS}$	: Row Address Strobe
$\overline{CAS}$	: Column Address Strobe
$\overline{WE}$	: Write Enable
$\overline{OE}$	: Output Enable
Vcc	: Supply Voltage
GND	: Ground
NC	: No Connection

BLOCK DIAGRAM



Notes 1.

Part number	Row address	Column address
μPD42S16400, 4216400	A0 to A11	A0 to A9
μPD42S17400, 4217400	A0 to A10	A0 to A10

2. μPD42S16400, 4216400...4 096×1 024×4 μPD42S17400, 4217400...2 048×2 048×4

INPUT/OUTPUT PIN FUNCTIONS

The μPD42S16400, 4216400, 42S17400, 4217400 have input pins $\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$, A0 to A11/A10 [Note1] and input/output pins I/O1 to I/O4.

Pin name	Input/ Output	Function
$\overline{RAS}$ (Row address strobe)	Input	$\overline{RAS}$ activates the sense amplifier by latching a row address and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address. It also selects the following function. • $\overline{CAS}$ before $\overline{RAS}$ refresh.
$\overline{CAS}$ (Column address strobe)		$\overline{CAS}$ activates data input/output circuit by latching column address and selecting a digit line connected with the sense amplifier.
A0 to A11/A10 [Note1] (Address input)		Address bus. Input total 22-bit of address signal, upper 12/11 [Note2] -bit and lower 10/11 [Note3] -bit in sequence (address multiplex method). Therefore, one word is selected from 4 194 304-word by 4-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{RAS}$. Then, switch the address bus to column address and activate $\overline{CAS}$. Each address is taken into the device when $\overline{RAS}$ and $\overline{CAS}$ are activated. Therefore, the address input setup time (t_{ASR}, t_{ASC}) and hold time (t_{RAH}, t_{CAH}) are specified for the activation of $\overline{RAS}$ and $\overline{CAS}$.
$\overline{WE}$ (Write enable)		Write control signal. Write operation is executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{WE}$.
$\overline{OE}$ (Output enable)		Read control signal. Read operation can be executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{OE}$. If $\overline{WE}$ is activated during read operation, $\overline{OE}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O4 (Data input/output)	Input/ Output	4-bit data bus. I/O1 to I/O4 are used to input/output data.

Notes 1. A11 ··· μPD42S16400, 4216400 A10 ··· μPD42S17400, 4217400
2. 12 ··· μPD42S16400, 4216400 11 ··· μPD42S17400, 4217400
3. 10 ··· μPD42S16400, 4216400 11 ··· μPD42S17400, 4217400

ELECTRICAL SPECIFICATIONS Notes1, 2

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Voltage on any pin relative to GND	V_T		−1.0 to +7.0	V
Supply voltage	V_{CC}		−1.0 to +7.0	V
Output current	I_O		50	mA
Power dissipation	P_D		1	W
Operating temperature	T_{opt}		0 to +70	°C
Storage temperature	T_{stg}		−55 to +125	°C

Remark Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V_{CC}		4.5	5.0	5.5	V
High level input voltage	V_{IH}		2.4		V_{CC}+1.0	V
Low level input voltage	V_{IL}		−1.0		+0.8	V
Ambient temperature	T_a		0		70	°C

CAPACITANCE (T_a = +25 °C, f = 1 MHz)

[TSOP, SOJ]

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{I1}	A0 to A11			5	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			7	pF
Data Input/Output capacitance	$C_{I/O}$	I/O1 to I/O4			7	pF

[ZIP]

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{I1}	A0 to A11			7	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			9	pF
Data Input/Output capacitance	$C_{I/O}$	I/O1 to I/O4			9	pF

DC CHARACTERISTICS (Recommended Operating Conditions unless otherwise noted)

[μPD42S16400, 4216400]

Parameter		Symbol	Test condition		MIN.	MAX.	Unit	Notes
Operating current		I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ Cycling $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		100	mA	3,4,7
				t_{RAC} = 60 ns		90		
				t_{RAC} = 70 ns		80		
				t_{RAC} = 80 ns		70		
★ Standby current	μPD42S16400	I_{CC2}	$V_{IH(MIN.)} \leqq \overline{RAS}$, $\overline{CAS}$	I_O = 0 mA		2	mA	
			V_{CC}−0.2 V $\leqq \overline{RAS}$, $\overline{CAS}$	I_O = 0 mA		0.25		
	μPD4216400		$V_{IH(MIN.)} \leqq \overline{RAS}$, $\overline{CAS}$	I_O = 0 mA		2		
			V_{CC}−0.2 V $\leqq \overline{RAS}$, $\overline{CAS}$	I_O = 0 mA		1		
$\overline{RAS}$ only refresh current		I_{CC3}	$\overline{RAS}$ Cycling $V_{IH(MIN.)} \leqq \overline{CAS}$ $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		100	mA	3,4,5,7
				t_{RAC} = 60 ns		90		
				t_{RAC} = 70 ns		80		
				t_{RAC} = 80 ns		70		
Operating current (Fast page mode)		I_{CC4}	$\overline{CAS}$ Cycling $\overline{RAS} \leqq V_{IL(MAX.)}$ $t_{PC} = t_{PC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		80	mA	3,4,6
				t_{RAC} = 60 ns		70		
				t_{RAC} = 70 ns		60		
				t_{RAC} = 80 ns		50		
$\overline{CAS}$ before $\overline{RAS}$ refresh current		I_{CC5}	$\overline{RAS}$ Cycling, $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		100	mA	3,4
				t_{RAC} = 60 ns		90		
				t_{RAC} = 70 ns		80		
				t_{RAC} = 80 ns		70		
★ $\overline{CAS}$ before $\overline{RAS}$ long refresh current (4 096 cycles/128 ms, only for μPD42S16400)		I_{CC6}	Standby : V_{CC}−0.2 V $\leqq \overline{RAS}$ $\overline{CAS}$ before $\overline{RAS}$ Refresh : 4 096 cycles/128 ms $\overline{RAS}$, $\overline{CAS}$: 0 V $\leqq V_{IL} \leqq$ 0.2 V V_{CC}−0.2 V $\leqq V_{IH} \leqq V_{IH(MAX.)}$ $\overline{WE}$, $\overline{OE}$: V_{IH} Address input : Don't care Output : Open	$t_{RAS} \leqq$ 300 ns		450	μA	3,4
★				$t_{RAS} \leqq$ 1 μs		600		
★ Self refresh current ($\overline{CAS}$ before $\overline{RAS}$ self refresh, only for μPD42S16400)		I_{CC7}	I_O = 0 mA $\overline{RAS}$, $\overline{CAS}$: 0 V $\leqq V_{IL} \leqq$ 0.2 V V_{CC}−0.2 V $\leqq V_{IH} \leqq V_{IH(MAX.)}$			250	μA	
Input leakage current		$I_{I(L)}$	V_I = 0 to 5.5 V all other pins not under test = 0 V		−10	+10	μA	
Output leakage current		$I_{O(L)}$	Outputs are disabled (Hi-Z) V_O = 0 to 5.5 V		−10	+10	μA	
High level output voltage		V_{OH}	I_O = −5.0 mA		2.4		V	
Low level output voltage		V_{OL}	I_O = +4.2 mA			0.4	V	

[μPD42S17400, 4217400]

Parameter		Symbol	Test condition		MIN.	MAX.	Unit	Notes
Operating current		I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ Cycling $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		120	mA	3,4,7
				t_{RAC} = 60 ns		110		
				t_{RAC} = 70 ns		100		
				t_{RAC} = 80 ns		90		
Standby current	μPD42S17400	I_{CC2}	$V_{IH(MIN.)} \leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		2	mA	★
			V_{CC}−0.2 V $\leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		0.25		
	μPD4217400		$V_{IH(MIN.)} \leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		2		
			V_{CC}−0.2 V $\leqq \overline{RAS}, \overline{CAS}$	I_O = 0 mA		1		
$\overline{RAS}$ only refresh current		I_{CC3}	$\overline{RAS}$ Cycling $V_{IH(MIN.)} \leqq \overline{CAS}$ $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		120	mA	3,4,5,7
				t_{RAC} = 60 ns		110		
				t_{RAC} = 70 ns		100		
				t_{RAC} = 80 ns		90		
Operating current (Fast page mode)		I_{CC4}	$\overline{CAS}$ Cycling $\overline{RAS} \leqq V_{IL(MAX.)}$ $t_{PC} = t_{PC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		80	mA	3,4,6
				t_{RAC} = 60 ns		70		
				t_{RAC} = 70 ns		60		
				t_{RAC} = 80 ns		50		
$\overline{CAS}$ before $\overline{RAS}$ refresh current		I_{CC5}	$\overline{RAS}$ Cycling, $t_{RC} = t_{RC(MIN.)}$ I_O = 0 mA	t_{RAC} = 50 ns		120	mA	3,4
				t_{RAC} = 60 ns		110		
				t_{RAC} = 70 ns		100		
				t_{RAC} = 80 ns		90		
$\overline{CAS}$ before $\overline{RAS}$ long refresh current (2 048 cycles/128 ms, only for μPD42S17400)		I_{CC6}	Standby : V_{CC}−0.2 V $\leqq \overline{RAS}$ $\overline{CAS}$ before $\overline{RAS}$ Refresh : 2 048 cycles/128 ms $\overline{RAS}$, $\overline{CAS}$: 0 V $\leqq V_{IL} \leqq$ 0.2 V V_{CC}−0.2 V $\leqq V_{IH} \leqq V_{IH(MAX.)}$ $\overline{WE}$, $\overline{OE}$: V_{IH} Address input : Don't care Output : Open	$t_{RAS} \leqq$ 300 ns		400	μA	3,4 ★
				$t_{RAS} \leqq$ 1 μs		500		★
Self refresh current ($\overline{CAS}$ before $\overline{RAS}$ self refresh, only for μPD42S17400)		I_{CC7}	I_O = 0 mA $\overline{RAS}$, $\overline{CAS}$: 0 V $\leqq V_{IL} \leqq$ 0.2 V V_{CC}−0.2 V $\leqq V_{IH} \leqq V_{IH(MAX.)}$			250	μA	★
Input leakage current		$I_{I(L)}$	V_I = 0 to 5.5 V all other pins not under test = 0 V		−10	+10	μA	
Output leakage current		$I_{O(L)}$	Outputs are disabled (Hi-Z) V_O = 0 to 5.5 V		−10	+10	μA	
High level output voltage		V_{OH}	I_O = −5.0 mA		2.4		V	
Low level output voltage		V_{OL}	I_O = +4.2 mA			0.4	V	

AC CHARACTERISTICS

(Recommended Operating Conditions unless otherwise noted) Notes 8, 9 (1/2)

Parameter	Symbol	t_{RAC} = 50 ns		t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read or Write Cycle Time	t_{RC}	90		110		130		150		ns	
Read Modify Write Cycle Time	t_{RWC}	140		160		180		205		ns	
Fast Page Mode Cycle Time (Read or Write)	t_{PC}	35		40		45		50		ns	
Read Modify Write Cycle Time (Fast Page Mode)	t_{PRWC}	80		85		90		105		ns	
Access Time from $\overline{RAS}$	t_{RAC}		50		60		70		80	ns	10, 11
Access Time from $\overline{CAS}$ (Falling Edge)	t_{CAC}		13		15		18		20	ns	10, 11
Access Time from Column Address	t_{AA}		25		30		35		40	ns	10, 11
Access Time from $\overline{CAS}$ Precharge	t_{ACP}		30		35		40		45	ns	11
Access Time from $\overline{OE}$	t_{OEA}		13		15		18		20	ns	11
$\overline{RAS}$ to Column Address Delay Time	t_{RAD}	13	25	15	30	15	35	17	40	ns	10
$\overline{CAS}$ to Data Setup Time	t_{CLZ}	0		0		0		0		ns	11
$\overline{OE}$ to Data Setup Time	t_{OLZ}	0		0		0		0		ns	11
Output Buffer Turn-off Delay Time ($\overline{CAS}$)	t_{OFF}	0	10	0	15	0	15	0	20	ns	12
$\overline{OE}$ to Data Delay Time	t_{OED}	10		15		15		20		ns	
Output Buffer Turn-off Delay Time ($\overline{OE}$)	t_{OEZ}	0	10	0	15	0	15	0	20	ns	12
$\overline{OE}$ Command Hold Time	t_{OEH}	0		0		0		0		ns	
$\overline{OE}$ to $\overline{RAS}$ inactive Setup Time	t_{OES}	0		0		0		0		ns	
Transition Time (Rise and Fall)	t_T	3	50	3	50	3	50	3	50	ns	
$\overline{RAS}$ Precharge Time	t_{RP}	30		40		50		60		ns	
$\overline{RAS}$ Pulse Width (Random Read, Write Cycle)	t_{RAS}	50	10 000	60	10 000	70	10 000	80	10 000	ns	
$\overline{RAS}$ Pulse Width (Fast Page Mode)	t_{RASP}	50	125 000	60	125 000	70	125 000	80	125 000	ns	
$\overline{RAS}$ Hold Time	t_{RSH}	13		15		18		20		ns	
$\overline{CAS}$ Pulse Width	t_{CAS}	13	10 000	15	10 000	18	10 000	20	10 000	ns	
$\overline{CAS}$ Hold Time	t_{CSH}	50		60		70		80		ns	
$\overline{RAS}$ to $\overline{CAS}$ Delay Time	t_{RCD}	18	32	20	40	20	50	25	60	ns	10
$\overline{CAS}$ to $\overline{RAS}$ Precharge Time	t_{CRP}	5		5		5		5		ns	13
$\overline{CAS}$ Precharge Time	t_{CPN}	8		10		10		10		ns	
$\overline{CAS}$ Precharge Time (Fast Page Mode)	t_{CP}	8		10		10		10		ns	
$\overline{RAS}$ Precharge $\overline{CAS}$ Hold Time	t_{RPC}	5		5		5		5		ns	
$\overline{RAS}$ Hold Time from $\overline{CAS}$ Precharge	t_{RHCP}	30		35		40		45		ns	
Row Address Setup Time	t_{ASR}	0		0		0		0		ns	
Row Address Hold Time	t_{RAH}	8		10		10		12		ns	

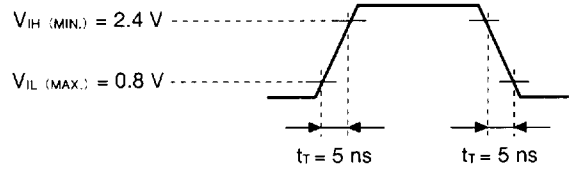
(2/2)

Parameter		Symbol	t_{RAC} = 50 ns		t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Notes
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Column Address Setup Time		t_{ASC}	0		0		0		0		ns	
Column Address Hold Time		t_{CAH}	13		15		15		15		ns	
Column Address Lead Time Referenced to $\overline{RAS}$		t_{RAL}	25		30		35		40		ns	
Read Command Setup Time		t_{RCS}	0		0		0		0		ns	
Read Command Hold Time Referenced to $\overline{RAS}$		t_{RRH}	0		0		0		0		ns	14
Read Command Hold Time Referenced to $\overline{CAS}$		t_{RCH}	0		0		0		0		ns	14
Write Command Hold Time Referenced to $\overline{CAS}$		t_{WCH}	8		10		10		15		ns	15
Write Command Pulse Width		t_{WP}	8		10		10		15		ns	15
Data-in Setup Time		t_{DS}	0		0		0		0		ns	16
Data-in Hold Time		t_{DH}	10		10		15		15		ns	16
$\overline{WE}$ Command Setup Time		t_{WCS}	0		0		0		0		ns	17
$\overline{CAS}$ to $\overline{WE}$ Delay Time		t_{CWD}	33		40		43		50		ns	17
$\overline{RAS}$ to $\overline{WE}$ Delay Time		t_{RWD}	70		85		95		110		ns	17
$\overline{CAS}$ Precharge Delay Time Referenced to $\overline{WE}$ (Fast Page Mode)		t_{CPWD}	50		58		65		70		ns	17
Column Address Delay Time Referenced to $\overline{WE}$		t_{AWD}	45		55		60		70		ns	17
Write Command Lead Time Referenced to $\overline{RAS}$		t_{RWL}	18		20		20		20		ns	
Write Command Lead Time Referenced to $\overline{CAS}$		t_{CWL}	13		15		15		15		ns	
$\overline{CAS}$ Setup Time for $\overline{CAS}$ before $\overline{RAS}$ Refresh		t_{CSR}	5		5		5		5		ns	
$\overline{CAS}$ Hold Time for $\overline{CAS}$ before $\overline{RAS}$ Refresh		t_{CHR}	10		10		10		10		ns	
$\overline{RAS}$ Pulse Width ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh Cycle)		t_{RASS}	100		100		100		100		μs	18
$\overline{RAS}$ Precharge Time ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh Cycle)		t_{RPS}	90		110		130		150		ns	18
$\overline{CAS}$ Hold Time ($\overline{CAS}$ before $\overline{RAS}$ Self Refresh Cycle)		t_{CHS}	−50		−50		−50		−50		ns	18
$\overline{WE}$ Setup Time		t_{WSR}	10		10		10		10		ns	
$\overline{WE}$ Hold Time		t_{WHR}	15		15		15		15		ns	
Refresh Time	μPD42S16400, 42S17400	t_{REF}		128		128		128		128	ms	18 ★
	μPD4216400			64		64		64		64		
	μPD4217400			32		32		32		32		

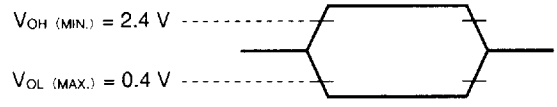
Notes

1. All voltages are referenced to GND.
2. After power up, wait more than 100 μs ($\overline{RAS}$, $\overline{CAS}$ inactive) and then, execute eight $\overline{CAS}$ before $\overline{RAS}$ or $\overline{RAS}$ only refresh cycles as dummy cycles to initialize internal circuit.
3. I_{CC1}, I_{CC3}, I_{CC4}, I_{CC5} and I_{CC6} depend on cycle rates (t_{RC} and t_{PC}).
4. Specified values are obtained with outputs unloaded.
5. I_{CC3} is measured assuming that all column address inputs are held at either high or low.
6. I_{CC4} is measured assuming that all column address inputs are switched only once during each fast page cycle.
7. I_{CC1} and I_{CC3} are measured assuming that address can be changed once or less during $\overline{RAS} \leqq V_{IL}$ (MAX.) and $\overline{CAS} \geqq V_{IH}$ (MIN.).
8. AC measurements assume t_T = 5 ns.
9. AC Characteristics test condition

(1) Input timing specification



(2) Output timing specification



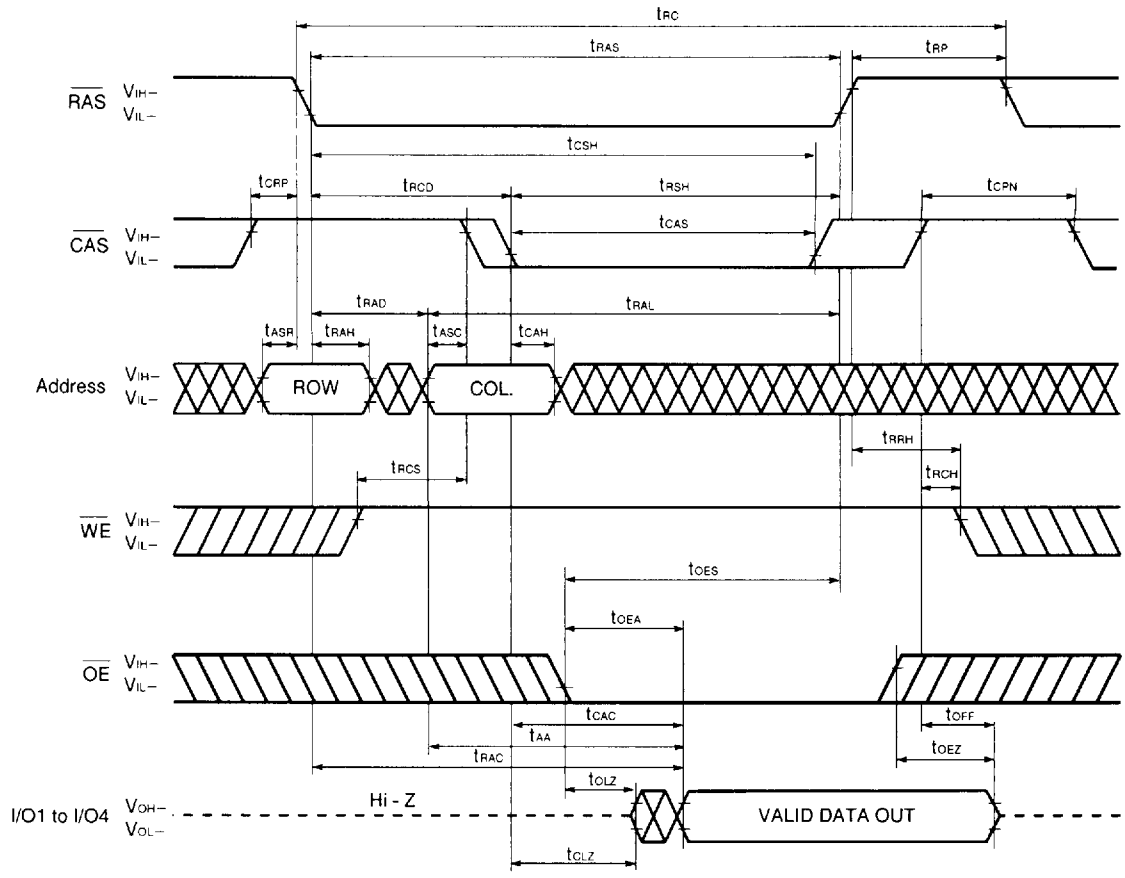
10. For read cycles, access time is defined as follows :

Input Conditions	Access Time	Access Time from $\overline{RAS}$
$t_{RAD} \leqq t_{RAD}$ (MAX.), $t_{RCD} \leqq t_{RCD}$ (MAX.)	t_{RAC} (MAX.)	t_{RAC} (MAX.)
$t_{RAD} > t_{RAD}$ (MAX.), $t_{RCD} \leqq t_{RCD}$ (MAX.)	t_{AA} (MAX.)	$t_{RAD} + t_{AA}$ (MAX.)
$t_{RCD} > t_{RCD}$ (MAX.)	t_{CAC} (MAX.)	$t_{RCD} + t_{CAC}$ (MAX.)

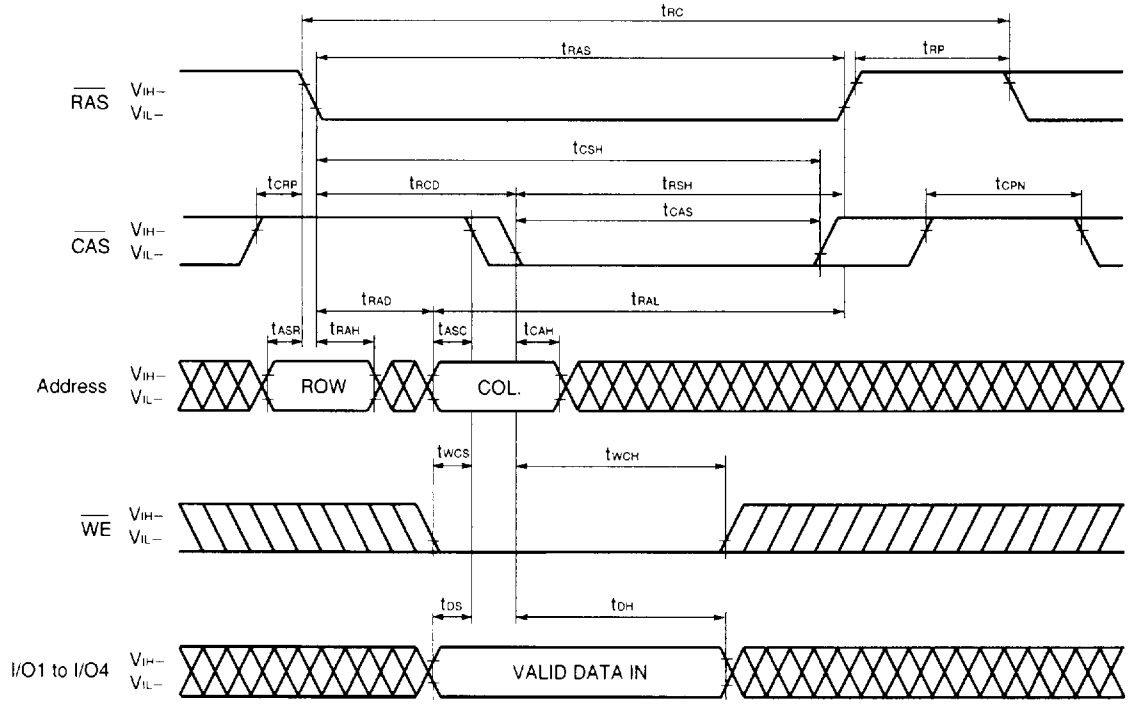
t_{RAD} (MAX.) and t_{RCD}(MAX.) are specified as reference points only ; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geqq t_{RAD}$ (MAX.) and $t_{RCD} \geqq t_{RCD}$ (MAX.) will not cause any operation problems.

11. Loading conditions are 2 TTLs and 100 pF.
12. t_{OFF} (MAX.) and t_{OEZ} (MAX.) define the time at which the output achieves the condition of Hi-Z and are not referenced to V_{OH} or V_{OL}.
13. t_{CRP} (MIN.) requirement should be applied for $\overline{RAS}$ / $\overline{CAS}$ cycles preceded by any cycles.
14. Either t_{RCH} (MIN.) or t_{RRH} (MIN.) should be met in read cycles.
15. t_{WP} (MIN.) is applied for late write cycles or read modify write cycles. In early write cycles, t_{WCH} (MIN.) should be met.
16. t_{DS} (MIN.) and t_{DH} (MIN.) are referenced to the $\overline{CAS}$ falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the $\overline{WE}$ falling edge.
17. If $t_{WCS} \geqq t_{WCS}$ (MIN.), the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geqq t_{RWD}$ (MIN.), $t_{CWD} \geqq t_{CWD}$ (MIN.), $t_{AWD} \geqq t_{AWD}$(MIN.) and $t_{CPWD} \geqq t_{CPWD}$(MIN.), the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.
18. This specification is applied only for the μPD42S16400 and μPD42S17400.

READ CYCLE

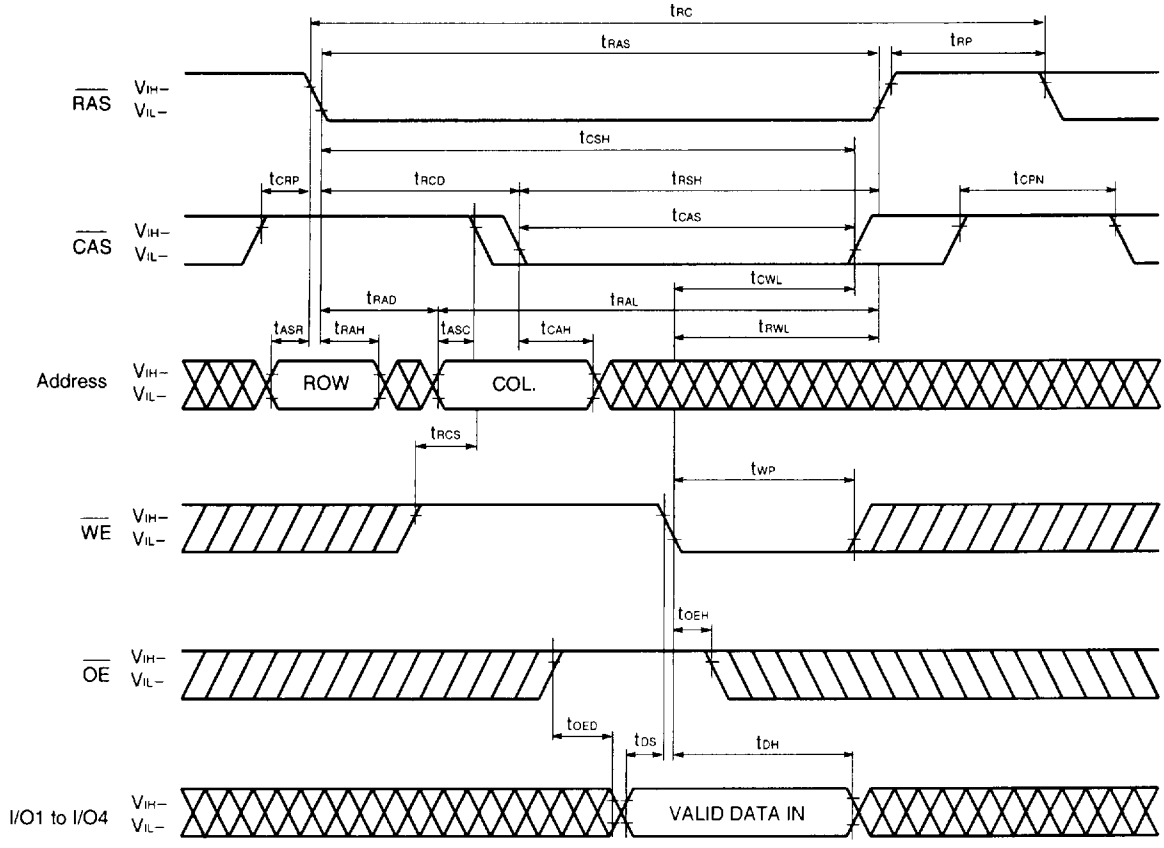


EARLY WRITE CYCLE

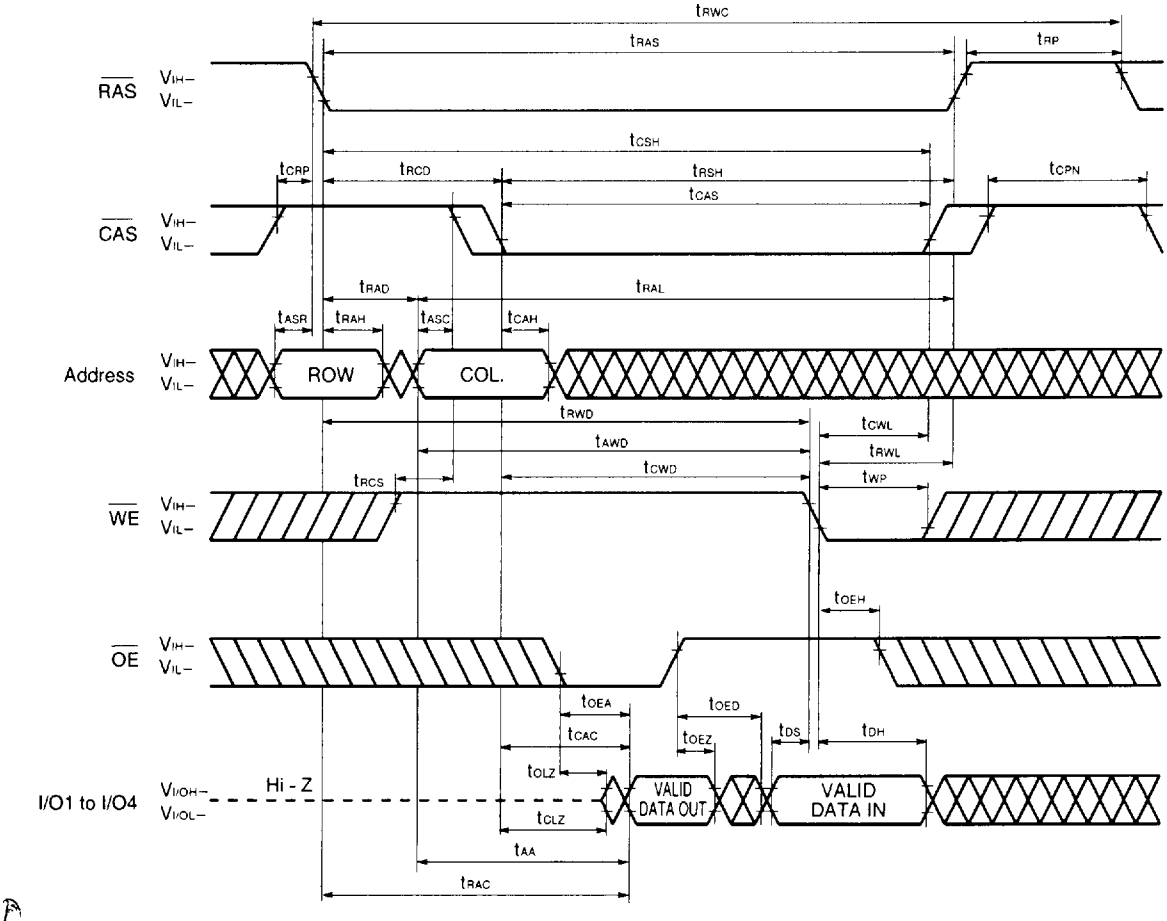


Remark $\overline{OE}$ = Don't Care

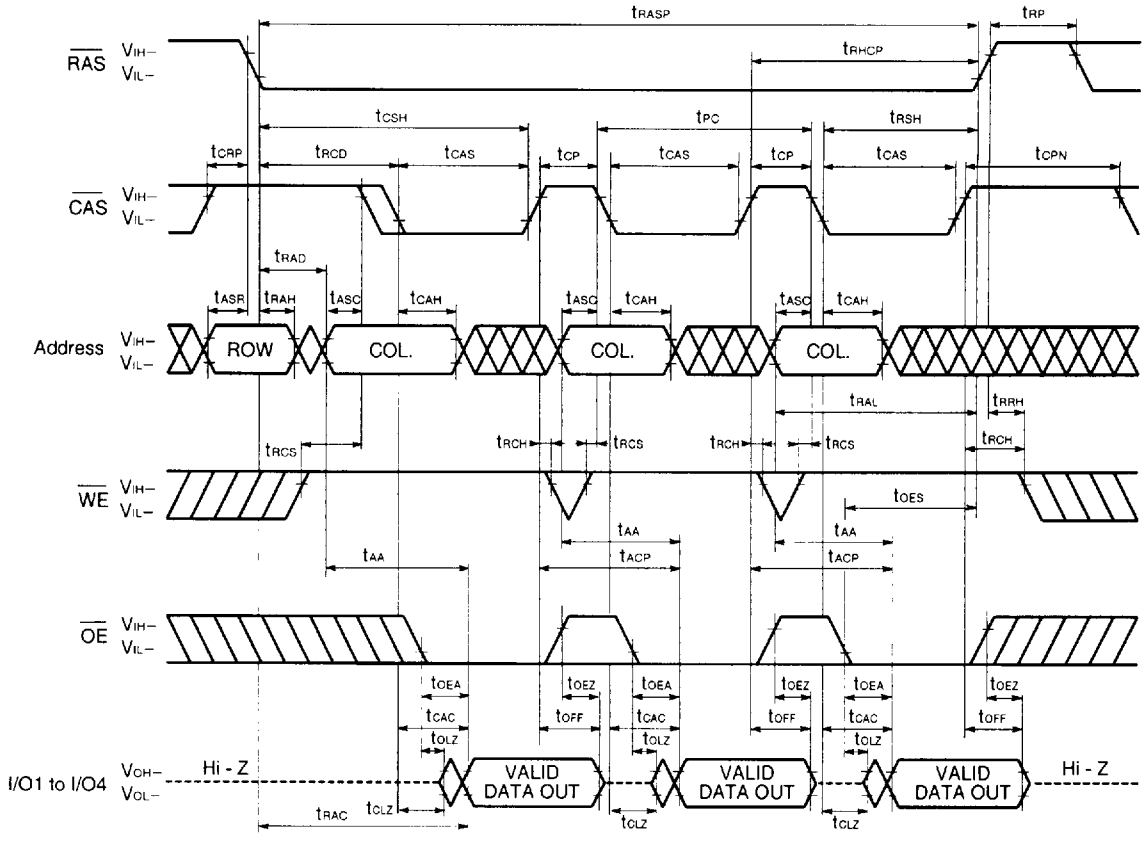
LATE WRITE CYCLE



★ READ MODIFY WRITE CYCLE

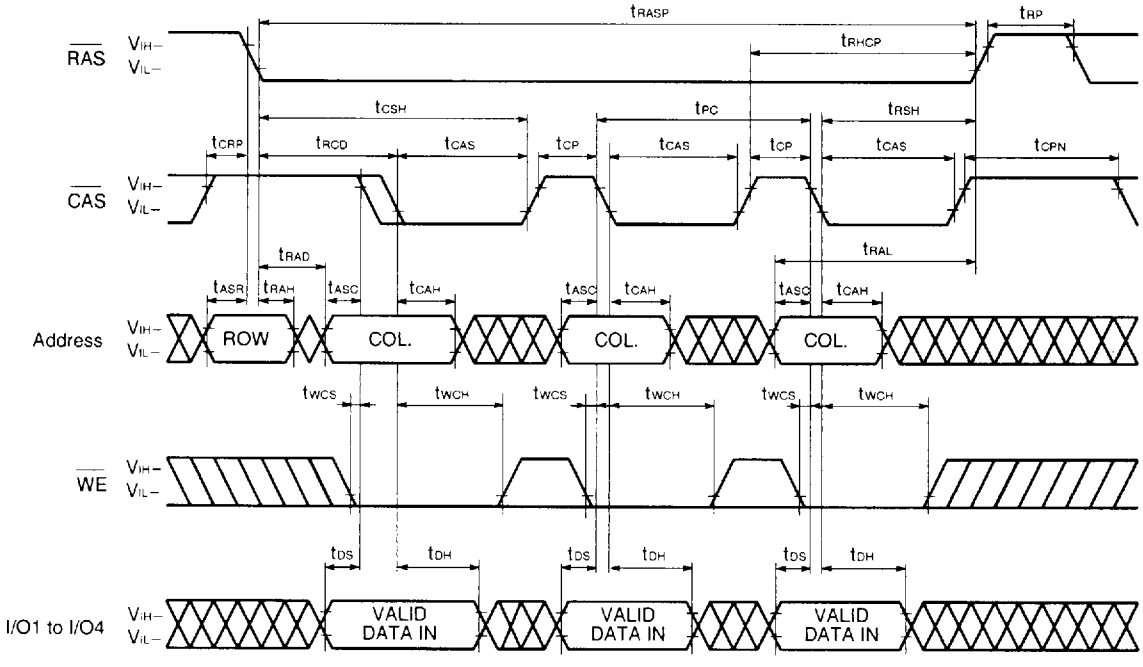


FAST PAGE MODE READ CYCLE



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

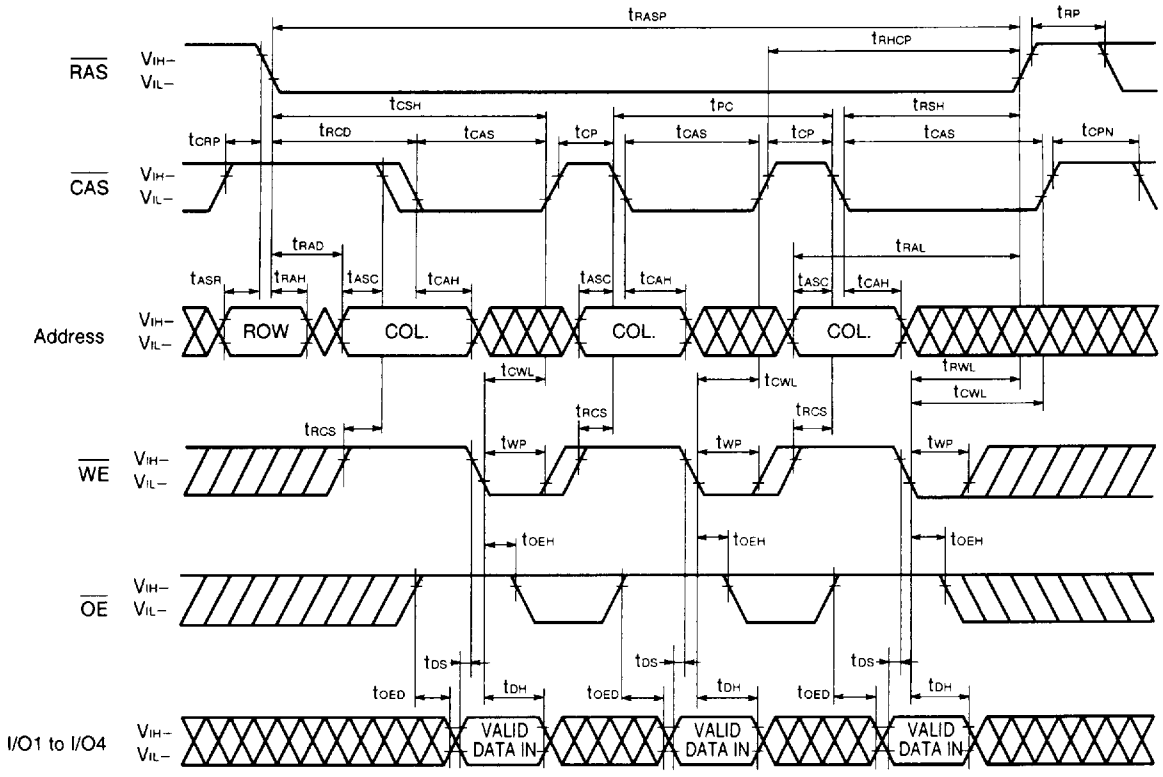
FAST PAGE MODE EARLY WRITE CYCLE



Remark $\overline{OE}$ = Don't Care

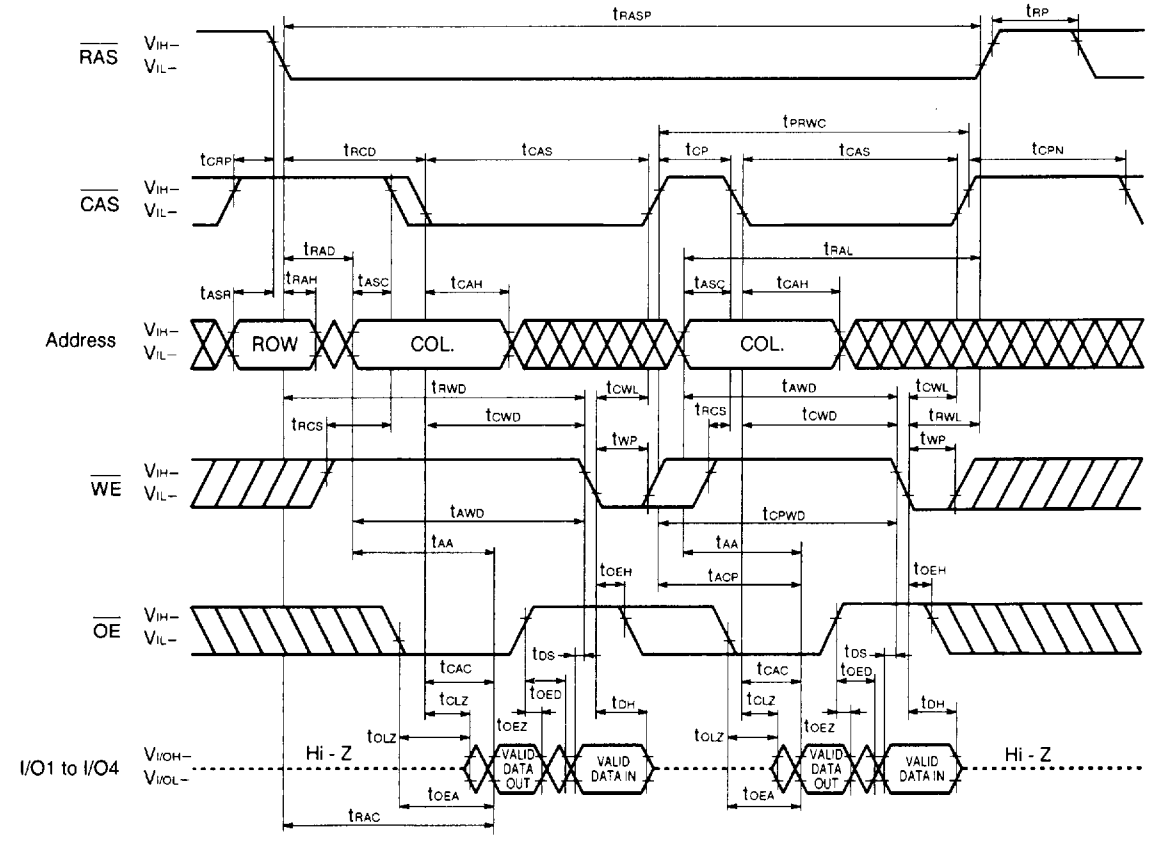
In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

FAST PAGE MODE LATE WRITE CYCLE



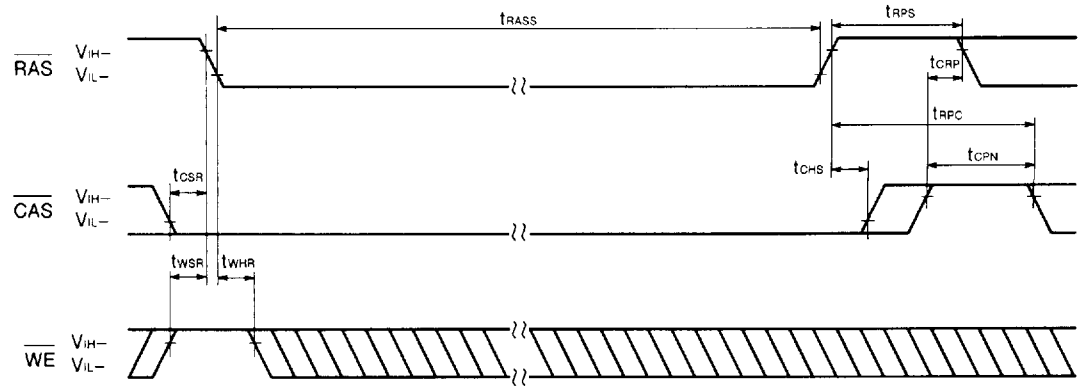
Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

★ FAST PAGE MODE READ MODIFY WRITE CYCLE



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

$\overline{CAS}$ BEFORE $\overline{RAS}$ SELF REFRESH CYCLE (Only for μPD42S16400, 42S17400)



Remark Address, $\overline{OE}$ = Don't care I/O1 to I/O4 = Hi - Z

How to use $\overline{CAS}$ before $\overline{RAS}$ self refresh mode

$\overline{CAS}$ before $\overline{RAS}$ self refresh mode can't be used by itself. It must be used with perfoming one of 3 refreshes below.

- **When using distributed $\overline{CAS}$ before $\overline{RAS}$ refresh** ★

  Refresh 4 096 times (μPD42S16400) or 2 048 times (μPD42S17400) during 128 ms before set into the $\overline{CAS}$ before $\overline{RAS}$ self refresh mode and after reset.

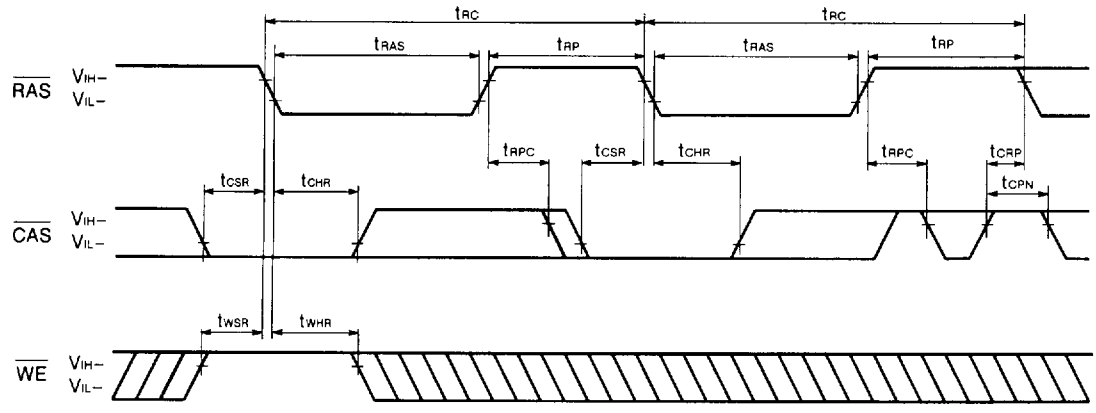
- **When using burst $\overline{CAS}$ before $\overline{RAS}$ refresh**

  Refresh 4 096 times during 64 ms (μPD42S16400) or 2 048 times during 32 ms (μPD42S17400) before set into the $\overline{CAS}$ before $\overline{RAS}$ self refresh mode and after reset.

- **When using $\overline{RAS}$ only refresh**

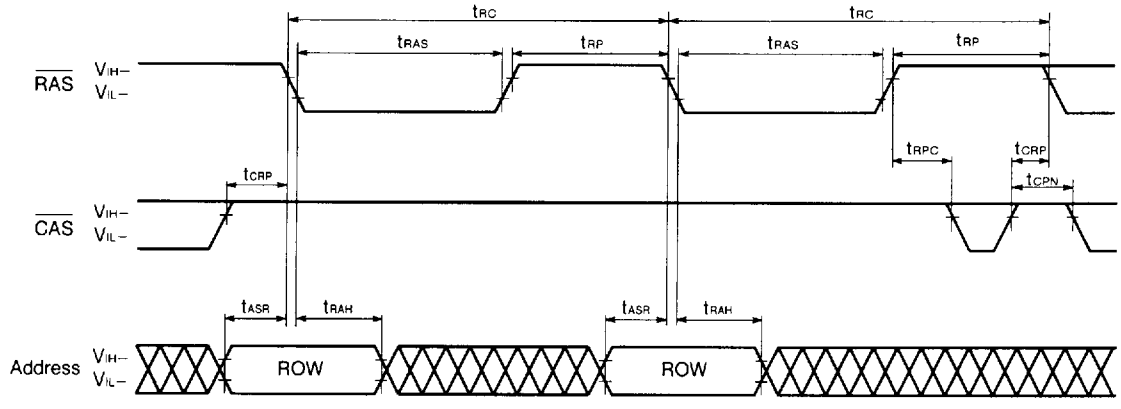
  Refresh against all refresh addresses during 64 ms (μPD42S16400) or during 32 ms (μPD42S17400) before set into the $\overline{CAS}$ before $\overline{RAS}$ self refresh mode and after reset.

$\overline{CAS}$ BEFORE $\overline{RAS}$ REFRESH CYCLE



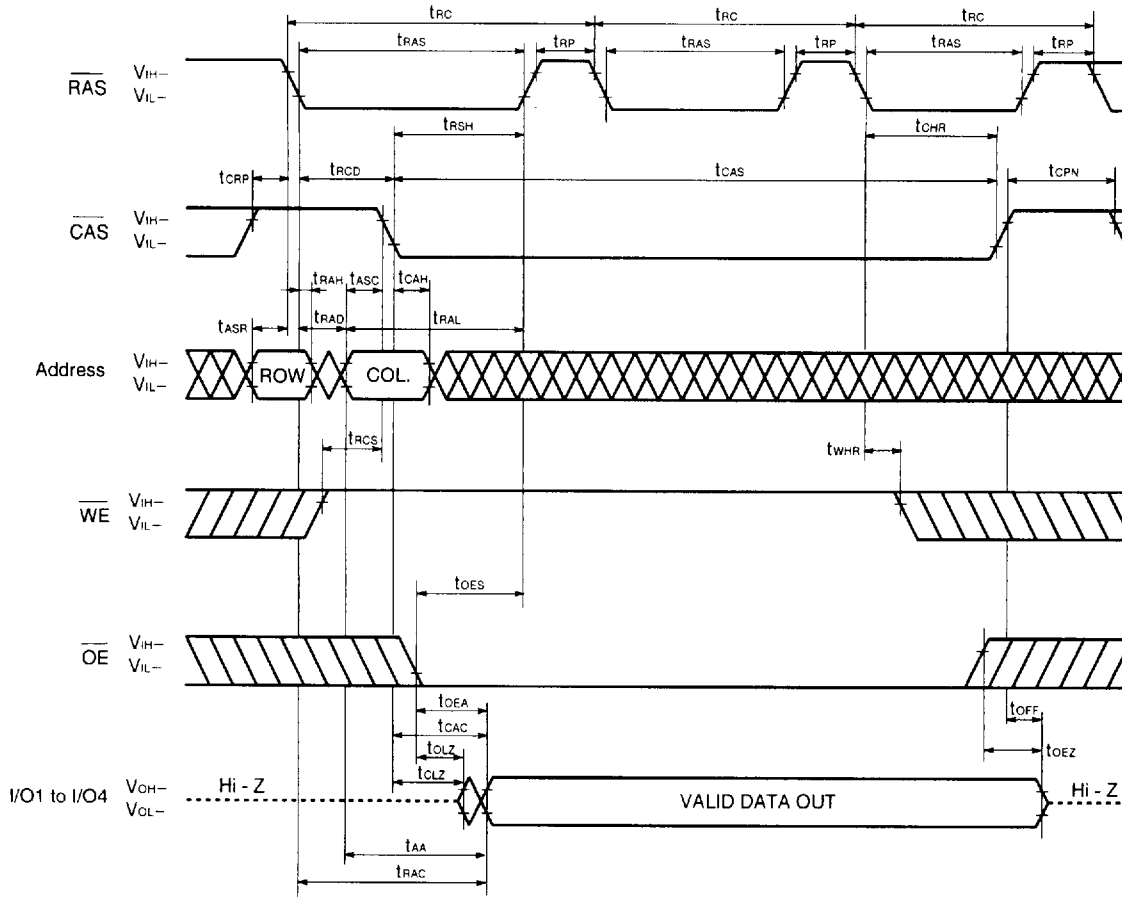
Remark Address, $\overline{OE}$ = Don't care I/O1 to I/O4 = Hi - Z

$\overline{RAS}$ ONLY REFRESH CYCLE

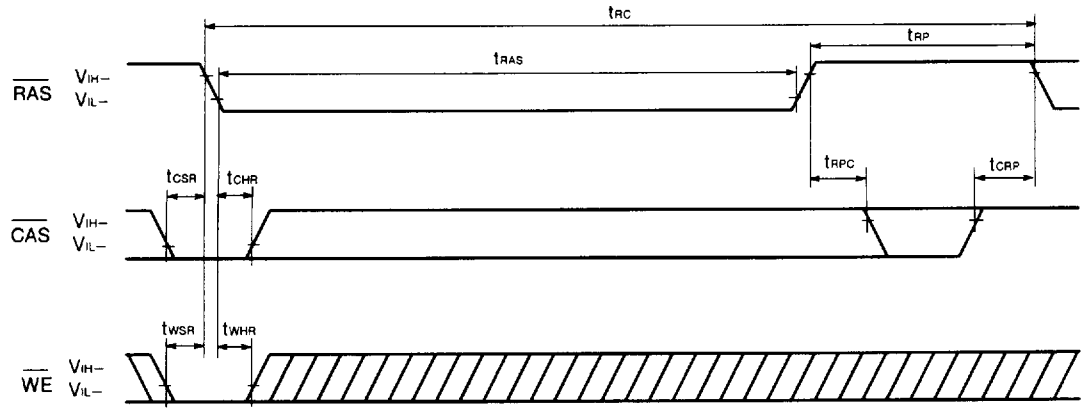


Remark $\overline{WE}$, $\overline{OE}$ = Don't care I/O1 to I/O4 = Hi - Z

HIDDEN REFRESH CYCLE



TEST MODE SET CYCLE ($\overline{WE}$ AND $\overline{CAS}$ BEFORE $\overline{RAS}$ REFRESH CYCLE)



Remark Address, $\overline{OE}$ = Don't care I/O1 to I/O4 = Hi - Z

TEST MODE

TEST MODE is fast test function. On using this mode, test time is reduced to 1/4. In this TEST MODE, internal organization is 1 M words by 16 bits apparently. Don't care about the input levels of the $\overline{CAS}$ input A0, A1.

1. How to enter TEST MODE

Through TEST MODE SET CYCLE ($\overline{WE}$ and $\overline{CAS}$ before $\overline{RAS}$ refresh cycle), the device enters TEST MODE.

2. Write / Read in TEST MODE

Write data of "1" or "0" through I/O1 to I/O4 by controlling address except for above-mentioned address. Each input data through each I/O write 4 bits at once. And read through I/O1 to I/O4 to check written data. In case of writing each 4 bits rightly, each I/O data is "1". But wrong, the data is "0".

3. Refresh in TEST MODE

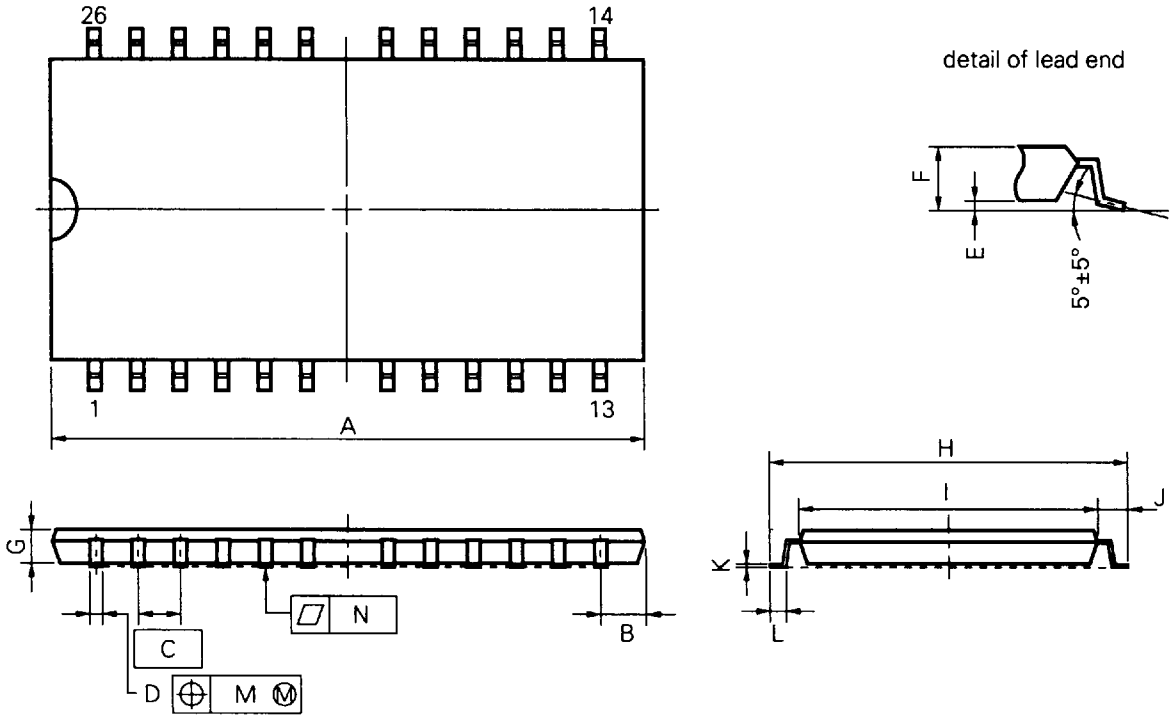
Use normal read cycle or $\overline{WE}$ and $\overline{CAS}$ before $\overline{RAS}$ refresh cycle.

4. How to exit from TEST MODE

Through $\overline{RAS}$ only refresh cycle or $\overline{CAS}$ before $\overline{RAS}$ refresh cycle, the device exits from TEST MODE.

PACKAGE DRAWINGS

26 PIN PLASTIC TSOP(II) (300 mil) ★

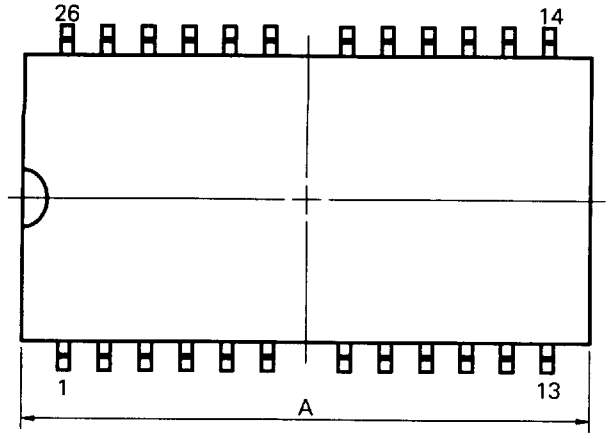


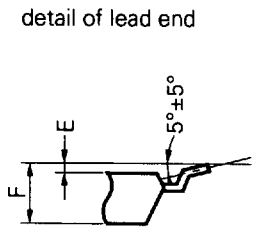
S26G3-50-7JD-1

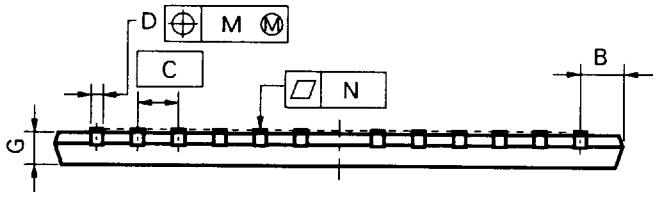
ITEM	MILLIMETERS	INCHES
A	17.40 MAX.	0.685 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	9.22 ± 0.2	0.363 ± 0.008
I	7.62 ± 0.1	0.300 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

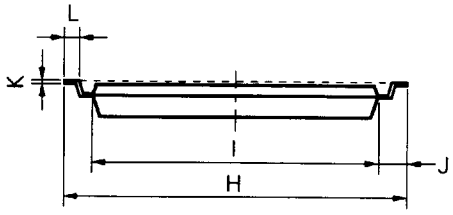
NOTE
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

★ 26 PIN PLASTIC TSOP(II) (300 mil)









S26G3-50-7KD-1

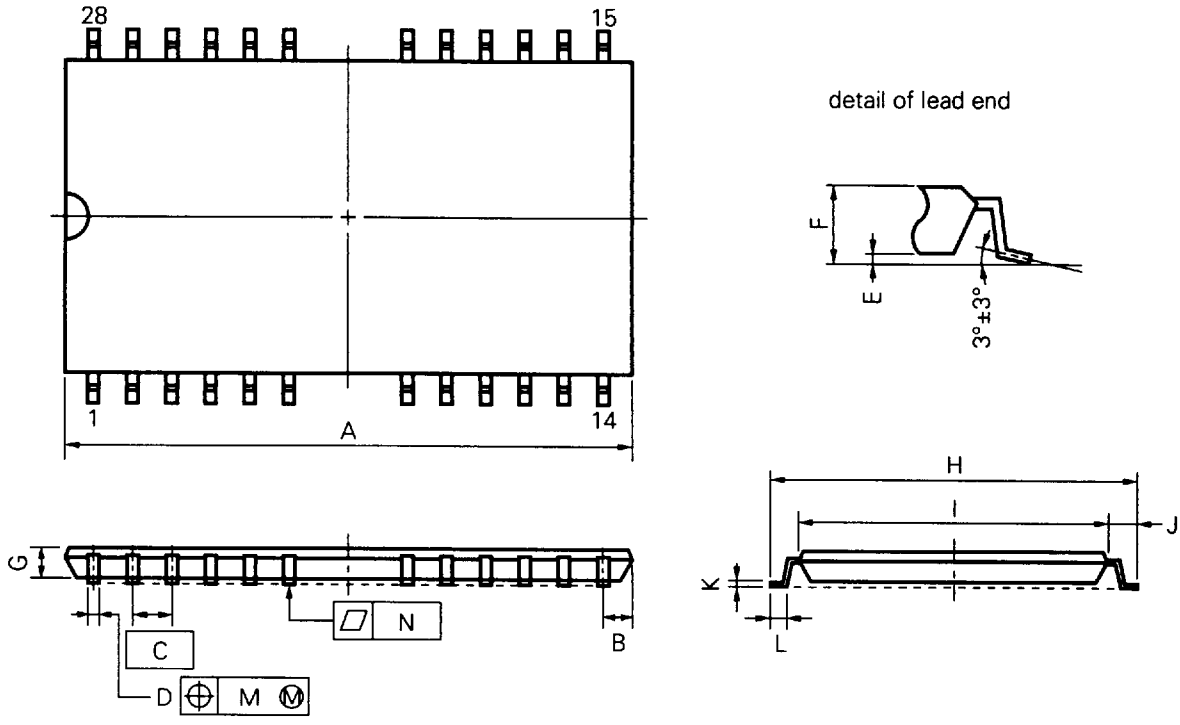
NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	17.40 MAX.	0.685 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	9.22 ± 0.2	0.363 ± 0.008
I	7.62 ± 0.1	0.300 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP(II) (400 mil)

★



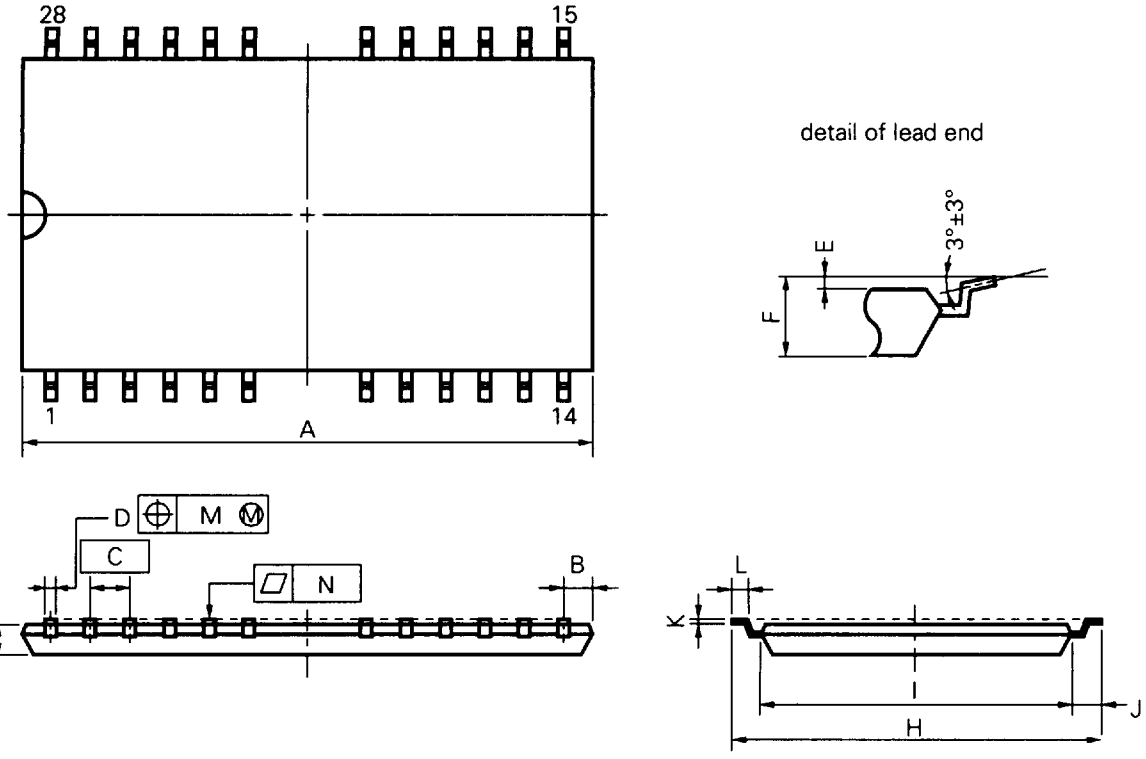
S28G5-50-7JD1-1

NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

★ 28 PIN PLASTIC TSOP(III) (400 mil)



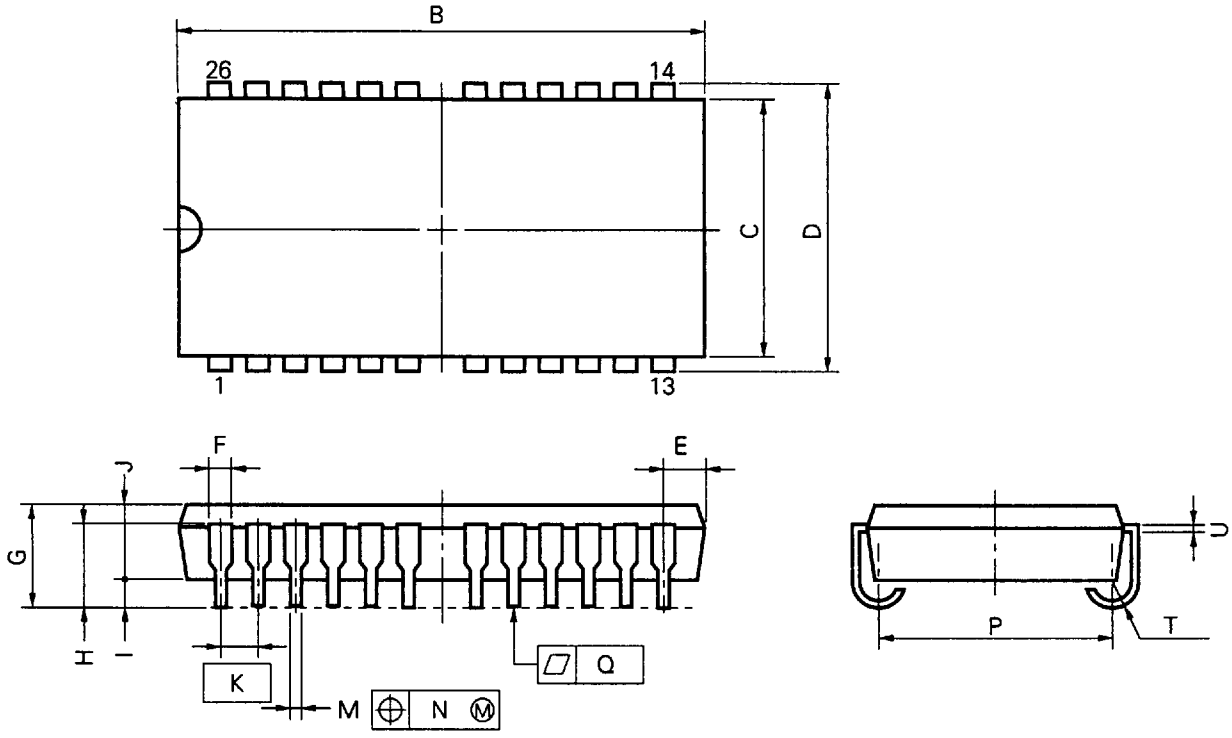
S28G5-50-7KD1-1

NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

26 PIN PLASTIC SOJ (300 mil)



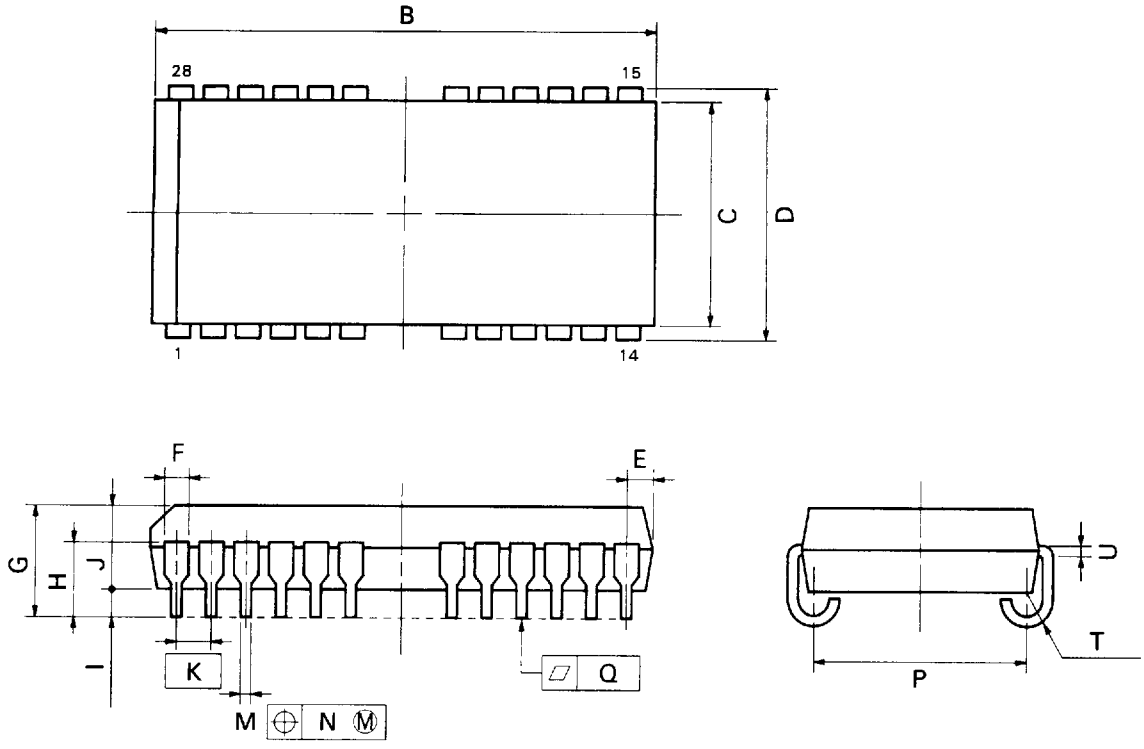
S26LA-300A

NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	$17.1^{+0.25}_{-0.05}$	$0.673^{+0.010}_{-0.002}$
C	7.62	0.300
D	8.47±0.2	$0.333^{+0.009}_{-0.008}$
E	1.03±0.15	$0.041^{+0.006}_{-0.007}$
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	6.73±0.20	0.265±0.008
Q	0.10	0.004
T	R 0.85	R 0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

28 PIN PLASTIC SOJ (400 mil)



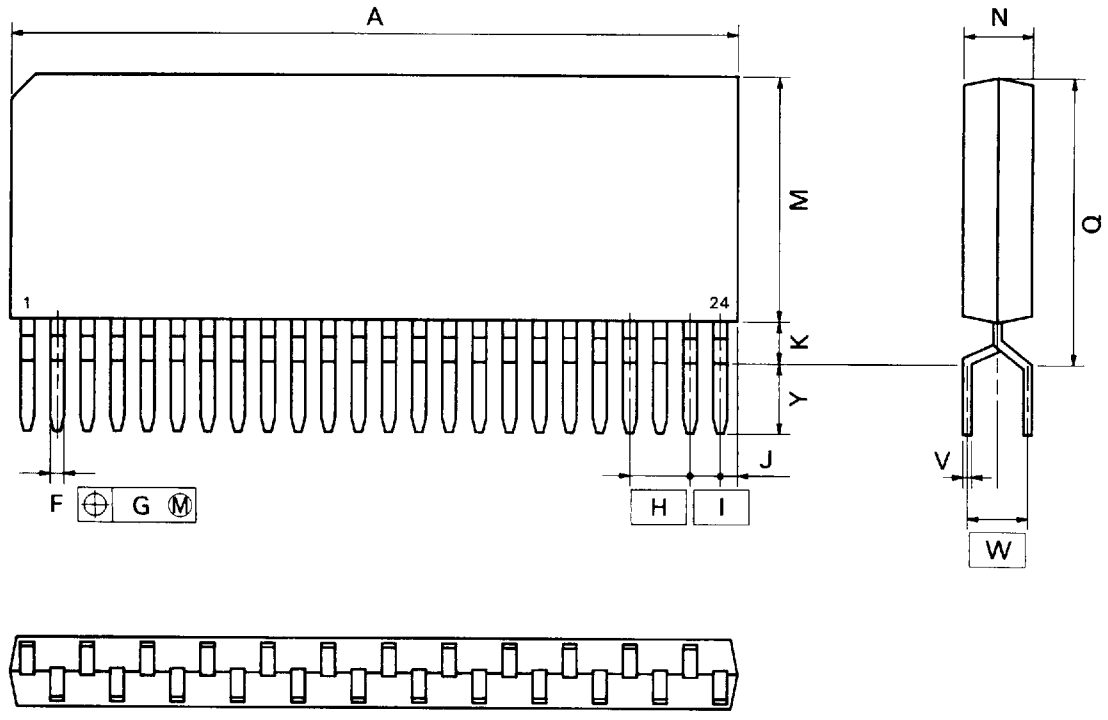
P28LE-400A

NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	$18.67^{+0.2}_{-0.35}$	$0.735^{+0.008}_{-0.013}$
C	10.16	0.400
D	$11.18^{+0.2}$	$0.440^{-0.008}_{0.007}$
E	$1.08^{+0.15}$	$0.043^{+0.006}_{-0.007}$
F	0.7	0.028
G	$3.5^{+0.2}$	$0.138^{+0.008}_{-0.007}$
H	$2.4^{+0.2}$	$0.094^{+0.009}_{-0.008}$
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	$0.40^{+0.10}$	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	$9.40^{+0.20}$	$0.370^{+0.008}_{0.007}$
Q	0.15	0.006
T	R0.85	R0.033
U	$0.20^{0.10}_{0.05}$	$0.008^{+0.004}_{-0.002}$

24 PIN PLASTIC ZIP (475 mil)



P24V-100-475A

NOTE

Each lead centerline is located within 0.25 mm (0.010 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	31.75 MAX.	1.250 MAX.
F	$0.50^{+0.1}$	$0.020^{+0.004}_{-0.005}$
G	ϕ0.25	ϕ0.010
H	2.54	0.100
I	1.27	0.050
J	1.27 MAX.	0.050 MAX.
K	1.0 MIN.	0.039 MIN.
M	10.8 MAX.	0.426 MAX.
N	$2.8^{\pm0.2}$	$0.110^{-0.009}_{-0.008}$
Q	12.07 MAX.	0.476 MAX.
V	$0.25^{+0.10}_{-0.05}$	$0.010^{+0.004}_{-0.003}$
W	2.54	0.100
Y	$3.3^{+0.5}$	$0.130^{\pm0.02}$

RECOMMENDED SOLDERING CONDITIONS

Please consult with our sales offices for soldering conditions of the μPD42S16400, 4216400, 42S17400, 4217400.

TYPE OF SURFACE MOUNT DEVICE

μPD42S16400G3, 4216400G3, 42S17400G3, 4217400G3 : 26-pin Plastic TSOP (II) (300 mil)
μPD4216400G5, 4217400G5 : 28-pin Plastic TSOP (II) (400 mil)
μPD42S16400LA, 4216400LA, 42S17400LA, 4217400LA : 26-pin Plastic SOJ (300 mil)
μPD4216400LE, 4217400LE : 28-pin Plastic SOJ (400 mil)

TYPE OF THROUGH HOLE MOUNT DEVICE

μPD4216400V, 4217400V : 24-pin Plastic ZIP (475 mil)

3. PACKAGE DRAWINGS

* : under development

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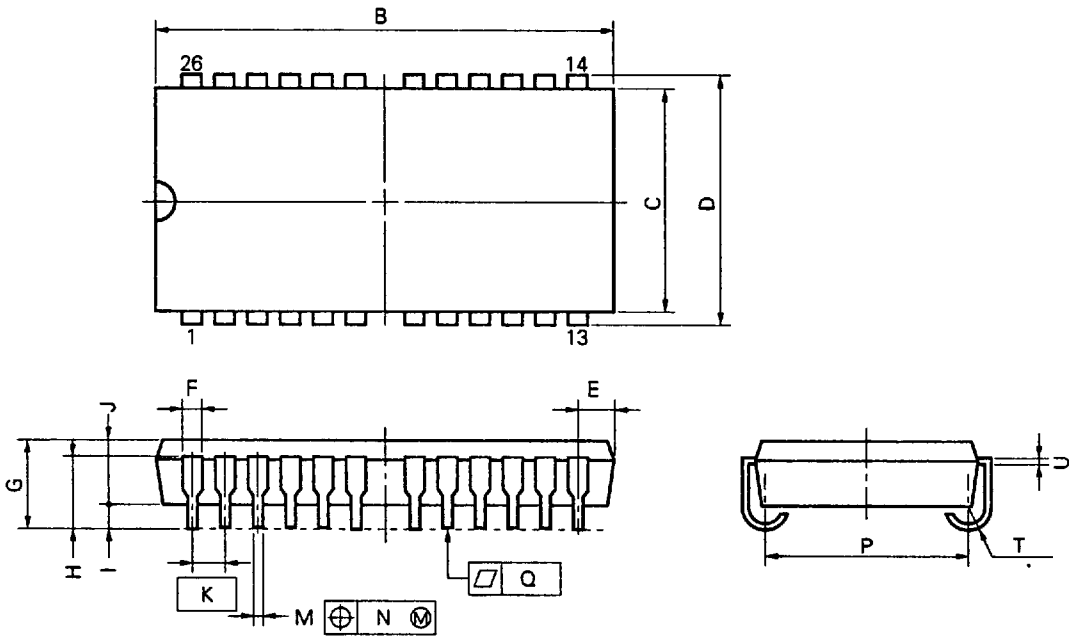
26 PIN PLASTIC SOJ (300mil)

24 Leads

NEC Cord:S26LA-300A



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

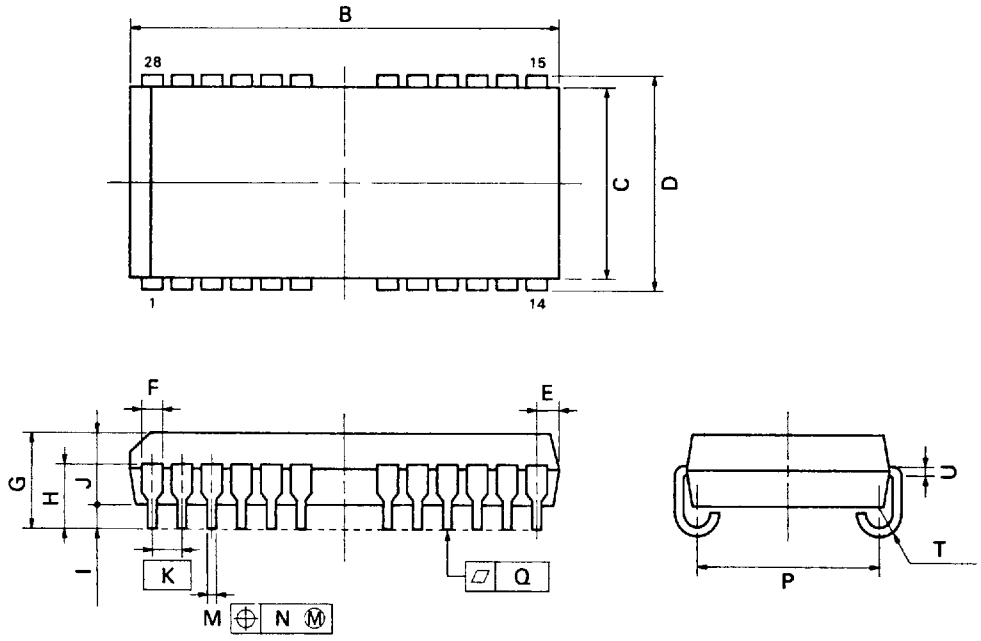
S26LA-300A

ITEM	MILLIMETERS	INCHES
B	$17.1^{+0.25}_{-0.05}$	$0.673^{+0.010}_{-0.002}$
C	7.62	0.300
D	8.47±0.2	$0.333^{+0.009}_{-0.008}$
E	1.03±0.15	$0.041^{+0.006}_{-0.007}$
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	6.73±0.20	0.265±0.008
Q	0.10	0.004
T	R 0.85	R 0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

28 PIN PLASTIC SOJ (400mil)

24 Leads

NEC Cord:P28LE-400A



P28LE-400A

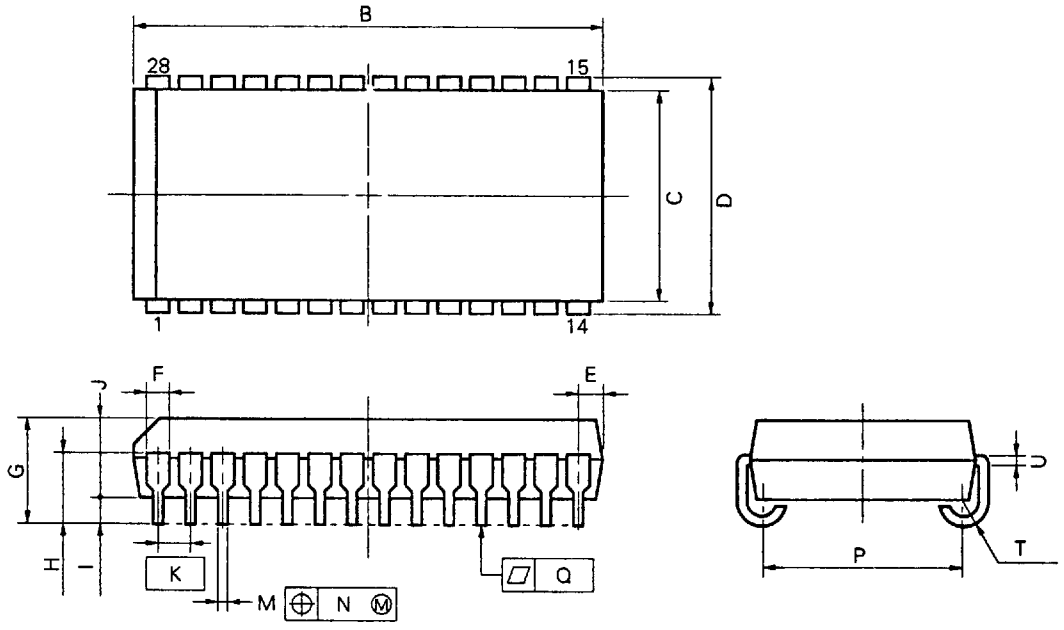
NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	18.67 $^{+0.2}_{-0.35}$	0.735 $^{+0.008}_{-0.013}$
C	10.16	0.400
D	11.18 $^{\pm 0.2}$	0.440 $^{+0.008}_{-0.007}$
E	1.08 $^{\pm 0.15}$	0.043 $^{+0.006}_{-0.007}$
F	0.7	0.028
G	3.5 $^{\pm 0.2}$	0.138 $^{+0.008}_{-0.007}$
H	2.4 $^{\pm 0.2}$	0.094 $^{+0.009}_{-0.008}$
I	0.8 MIN	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40 $^{\pm 0.10}$	0.016 $^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.40 $^{\pm 0.20}$	0.370 $^{+0.008}_{-0.007}$
Q	0.15	0.006
T	R0.85	R0.033
U	0.20 $^{+0.10}_{-0.05}$	0.008 $^{+0.004}_{-0.002}$

28 PIN PLASTIC SOJ (400mil)
28 Leads

NEC Cord:P28LE-400A1



NOTE

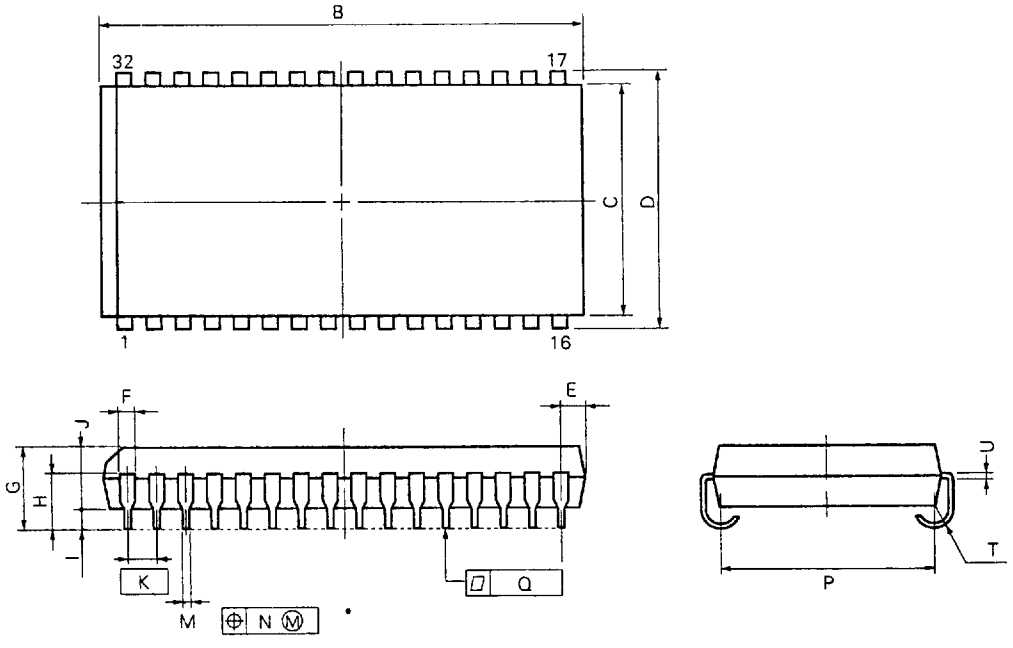
Each lead centerline is located within 0.12 mm (0 005 inch) of its true position (T.P.) at maximum material condition.

P28LE-400A1

ITEM	MILLIMETERS	INCHES
B	$18.67^{+0\ 2}_{-0\ 35}$	$0.735^{+0\ 008}_{-0\ 013}$
C	10.16	0.400
D	11.18±0.2	$0.440^{+0\ 008}_{-0\ 007}$
E	1.08±0.15	$0.043^{+0\ 006}_{-0\ 007}$
F	0.74	0.029
G	3.5±0.2	$0.138^{+0\ 008}_{-0\ 007}$
H	2.545±0.2	0.100±0.008
I	0.8 MIN	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P)	0 050 (T.P.)
M	0 40±0.10	$0.016^{+0\ 004}_{-0\ 005}$
N	0.12	0.005
P	9 40±0.20	$0.370^{+0\ 008}_{-0\ 007}$
Q	0.10	0.004
T	R 0 85	R 0.033
U	$0\ 20^{+0\ 10}_{-0\ 05}$	$0\ 008^{+0\ 004}_{-0\ 002}$

32 PIN PLASTIC SOJ (400mil)

NEC Cord:P32LE-400A



NOTE

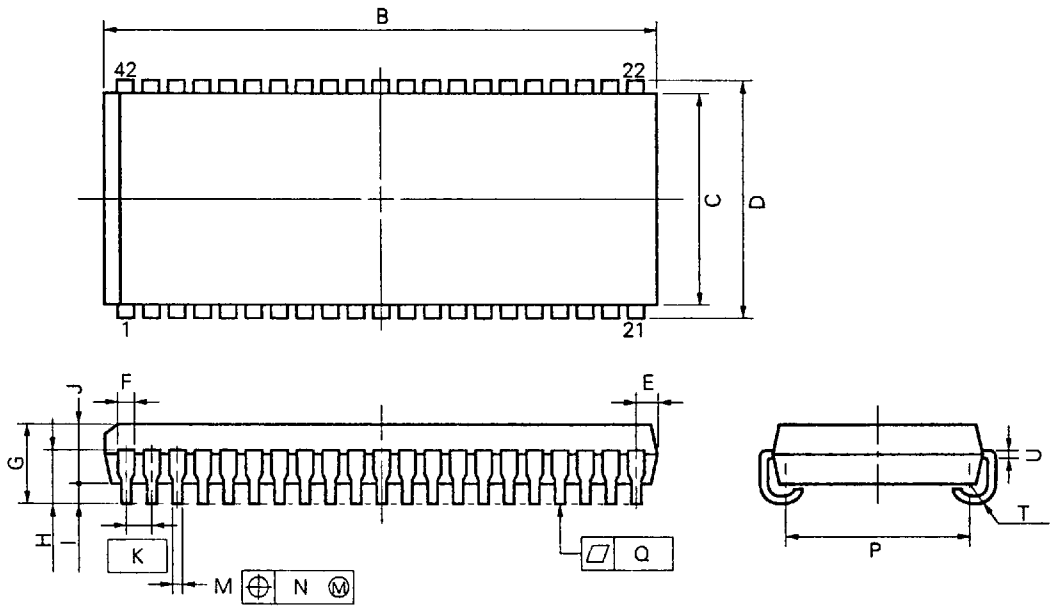
Each lead centerline is located within 0 12 mm (0 005 inch) of its true position (T P) at maximum material condition

P32LE-400A

ITEM	MILLIMETERS	INCHES
B	21.06±0 2	0 829±0 008
C	10 16	0 400
D	11 18±0 2	0.440±0 008
E	1 005±0.1	$0\ 040^{+0\ 004}_{-0\ 005}$
F	0.74	0 029
G	3.5±0.2	0 138±0 008
H	2 545±0 2	0 100±0.008
I	0 8 MIN	0 031 MIN
J	2 6	0.102
K	1 27 (T.P.)	0 050 (T P.)
M	0 40±0 10	$0\ 016^{+0\ 004}_{-0\ 005}$
N	0.12	0 005
P	9 4±0 20	0 370±0 008
Q	0.1	0.004
T	R 0 85	R 0.033
U	$0.20^{+0\ 10}_{-0\ 05}$	$0\ 008^{+0\ 004}_{-0\ 002}$

42 PIN PLASTIC SOJ (400mil)

NEC Cord:P42LE-400A



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

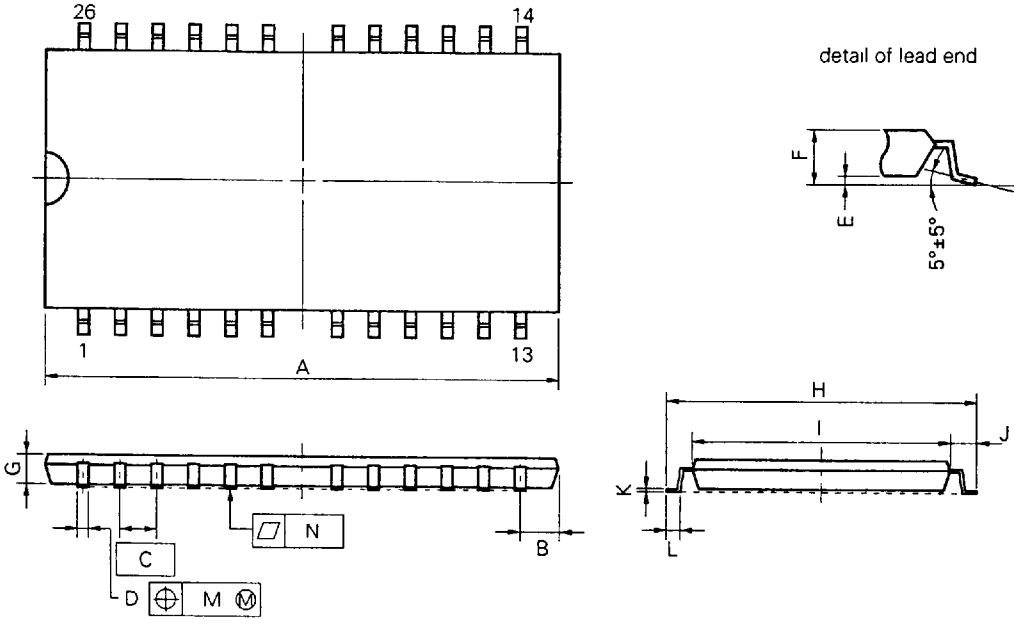
P42LE-400A

ITEM	MILLIMETERS	INCHES
B	$27.56^{+0.2}_{-0.35}$	$1.085^{+0.008}_{-0.014}$
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.08±0.15	$0.043^{+0.006}_{-0.007}$
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.10	0.004
T	R 0.85	R 0 033
U	$0\ 20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

26 PIN PLASTIC TSOP (300mil) *
24 Leads

* : under development

NEC Cord:S26G3-50-7JD



NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

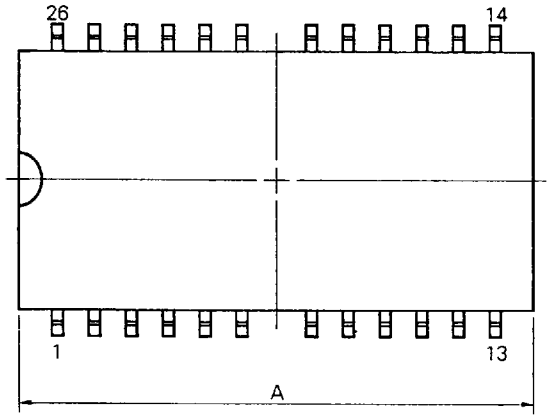
S26G3-50-7JD

ITEM	MILLIMETERS	INCHES
A	17.40 MAX.	0.685 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{+0.10}_{-0.05}$	$0.016^{+0.004}_{-0.005}$
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	9.22±0.2	0.363±0.008
I	7.62±0.1	0.300±0.004
J	$0.8^{+0.2}_{-0.1}$	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5±0.1	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

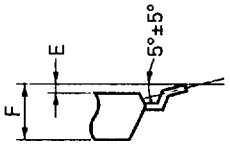
26 PIN PLASTIC TSOP (300mil) *
24 Leads Reverse bent

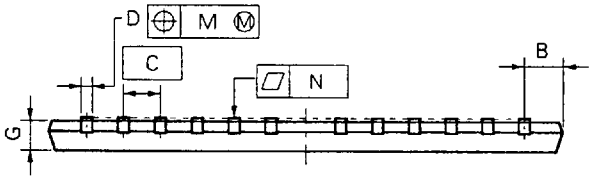
* : under development

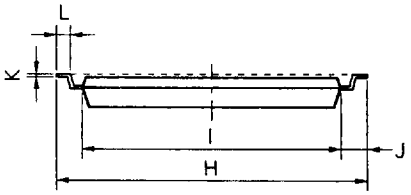
NEC Cord:S26G3-50-7KD



detail of lead end







S26G3-50-7KD

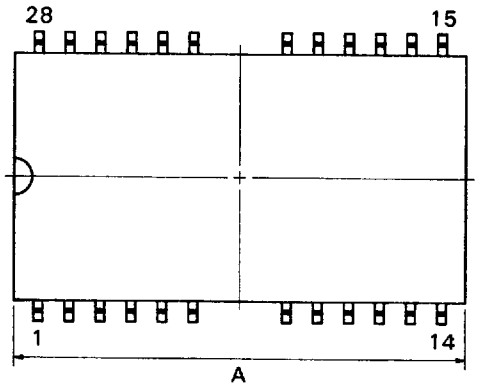
NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition

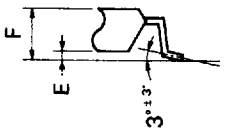
ITEM	MILLIMETERS	INCHES
A	17.40 MAX.	0.685 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T P)	0.050 (T.P.)
D	0 40±0.10	$0.016^{+0\ 004}_{-0\ 005}$
E	0.05±0.05	0.002±0.002
F	1.1 MAX.	0 044 MAX.
G	0 97	0.038
H	9.22±0.2	0.363±0.008
I	7.62±0.1	0.300±0.004
J	0.8±0 2	$0.031^{+0\ 009}_{-0\ 008}$
K	$0.125^{+0\ 10}_{-0\ 05}$	$0.005^{+0\ 004}_{-0\ 002}$
L	0 5±0.1	$0.020^{+0\ 004}_{-0\ 005}$
M	0.21	0.009
N	0 10	0 004

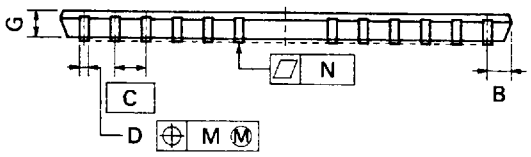
28 PIN PLASTIC TSOP (400mil)
24 Leads

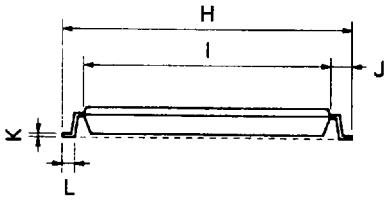
NEC Cord:S28G5-50-7JD1



detail of lead end







NOTE

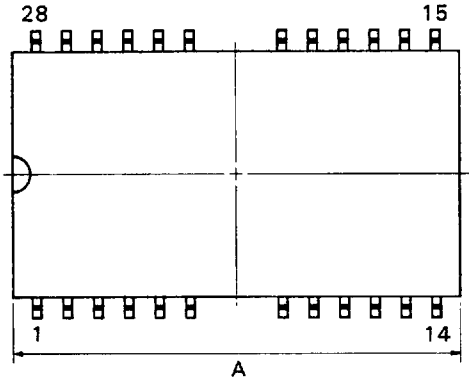
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

S28G5-50-7JD1

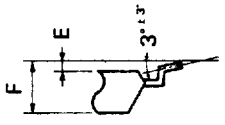
ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{\pm 0.10}$	$0.016^{+0.004}_{-0.005}$
E	$0.05^{\pm 0.05}$	$0.002^{\pm 0.002}$
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	$11.76^{\pm 0.2}$	$0.463^{\pm 0.008}$
I	$10.16^{\pm 0.1}$	$0.400^{\pm 0.004}$
J	$0.8^{\pm 0.2}$	$0.031^{+0.008}_{-0.009}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	$0.5^{\pm 0.1}$	$0.020^{+0.004}_{-0.005}$
M	0.21	0.009
N	0.10	0.004

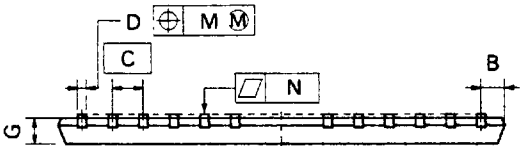
28 PIN PLASTIC TSOP (400mil)
24 Leads Reverse bent

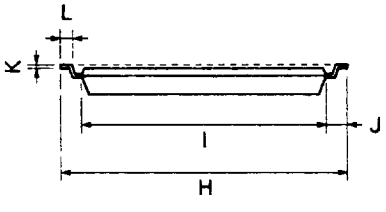
NEC Cord:S28G5-50-7KD1



detail of lead end







S28G5-50-7KD1

NOTE

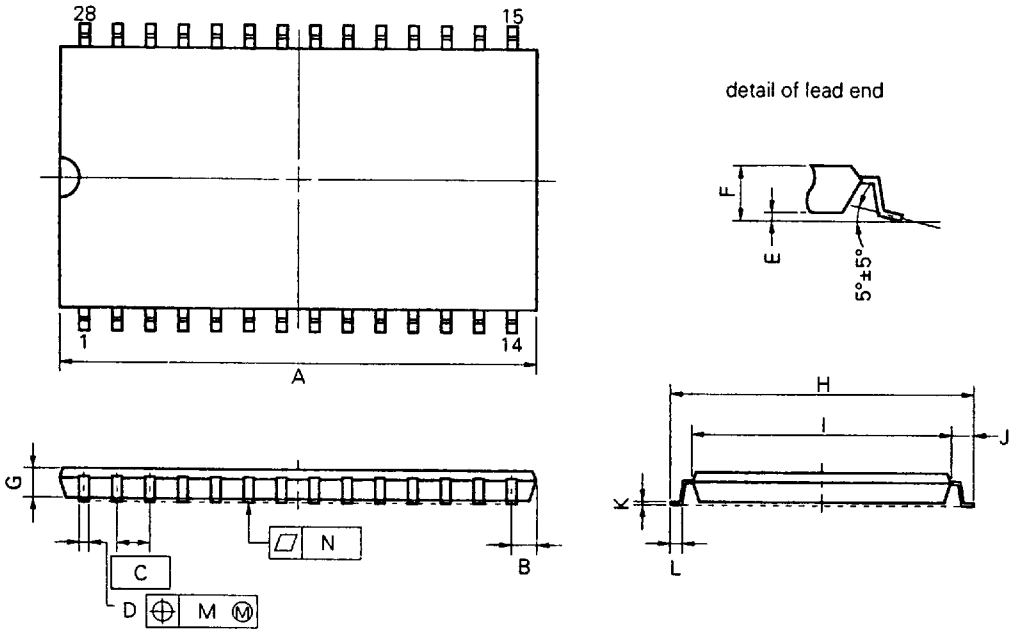
Each lead centerline is located within 0 21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	$0.40^{\pm 0\ 10}$	$0.016^{-0\ 004}_{-0\ 005}$
E	$0\ 05^{\pm 0\ 05}$	$0.002^{\pm 0\ 002}$
F	1 1 MAX.	0 044 MAX.
G	0 97	0.038
H	$11\ 76^{\pm 0\ 2}$	$0.463^{\pm 0\ 008}$
I	$10.16^{\pm 0\ 1}$	$0.400^{\pm 0\ 004}$
J	$0.8^{\pm 0\ 2}$	$0.031^{-0\ 009}_{-0\ 008}$
K	$0.125^{+0\ 10}_{-0\ 05}$	$0.005^{-0\ 004}_{-0\ 002}$
L	$0\ 5^{\pm 0\ 1}$	$0.020^{-0\ 004}_{-0\ 005}$
M	0.21	0.009
N	0.10	0.004

28 PIN PLASTIC TSOP (400mil)

28 Leads

NEC Cord:S28G5-50-7JD2



S28G5-50-7JD2

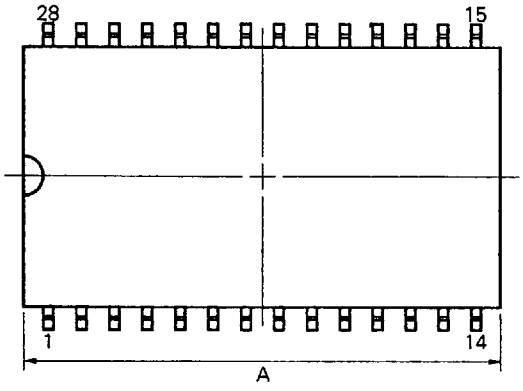
ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T P.)	0.050 (T.P.)
D	0.40±0.10	$0.016^{+0\ 004}_{-0\ 005}$
E	0 05±0.05	0.002±0.002
F	1.1 MAX.	0 044 MAX.
G	0.97	0.038
H	11.76±0.2	0 463±0.008
I	10 16±0.1	0 400±0 004
J	0.8±0 2	$0.031^{+0\ 009}_{-0\ 008}$
K	$0.125^{+0\ 10}_{-0\ 05}$	$0\ 005^{+0\ 004}_{-0\ 002}$
L	0.5±0 15	$0.020^{+0\ 006}_{-0\ 007}$
M	0.21	0.009
N	0.10	0.004

NOTE

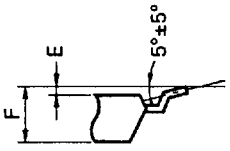
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

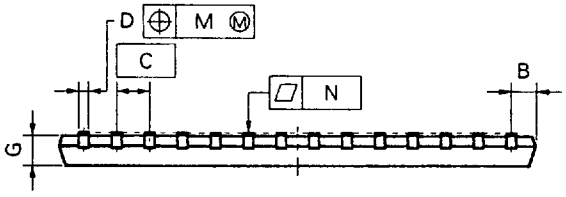
28 PIN PLASTIC TSOP (400mil)
28 Leads Reverse bent

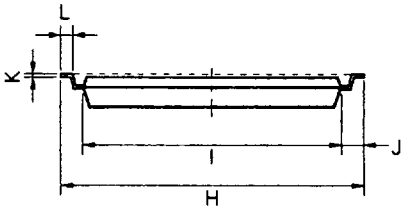
NEC Cord:S28G5-50-7KD2



detail of lead end







S28G5-50-7KD2

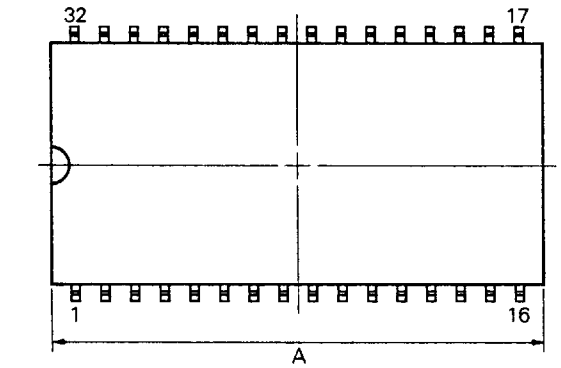
ITEM	MILLIMETERS	INCHES
A	18.81 MAX.	0.741 MAX.
B	1.15 MAX.	0.046 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0 40±0.10	$0.016^{+0\ 004}_{-0\ 005}$
E	0 05±0.05	0.002±0 002
F	1 1 MAX.	0.044 MAX.
G	0.97	0.038
H	11 76±0 2	0.463±0.008
I	10.16±0.1	0.400±0 004
J	0 8±0 2	$0\ 031^{+0\ 009}_{-0\ 008}$
K	$0.125^{+0\ 10}_{-0\ 05}$	$0.005^{+0\ 004}_{-0\ 002}$
L	0 5±0 15	$0\ 020^{+0\ 006}_{-0\ 007}$
M	0.21	0 009
N	0 10	0.004

NOTE

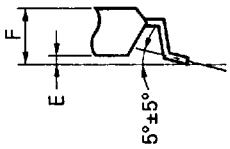
Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

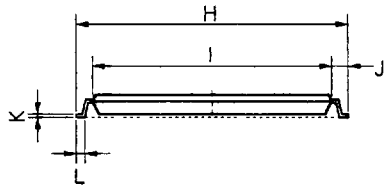
32 PIN PLASTIC TSOP (400mil)

NEC Cord:S32G5-50-7JD1



detail of lead end





S32G5-50-7JD1

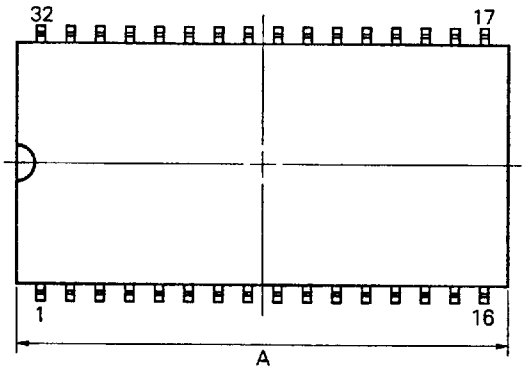
NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

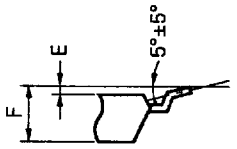
ITEM	MILLIMETERS	INCHES
A	21.17 MAX.	0.834 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.15	$0.020^{+0.006}_{-0.007}$
M	0.21	0.009
N	0.10	0.004

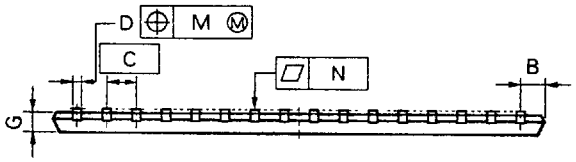
32 PIN PLASTIC TSOP (400mil)
Reverse bent

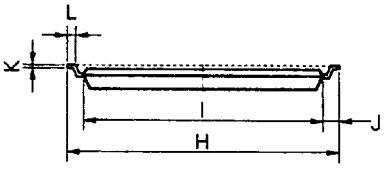
NEC Cord:S32G5-50-7KD1



detail of lead end







NOTE

Each lead centerline is located within 0.21 mm (0.009 inch) of its true position (T.P.) at maximum material condition.

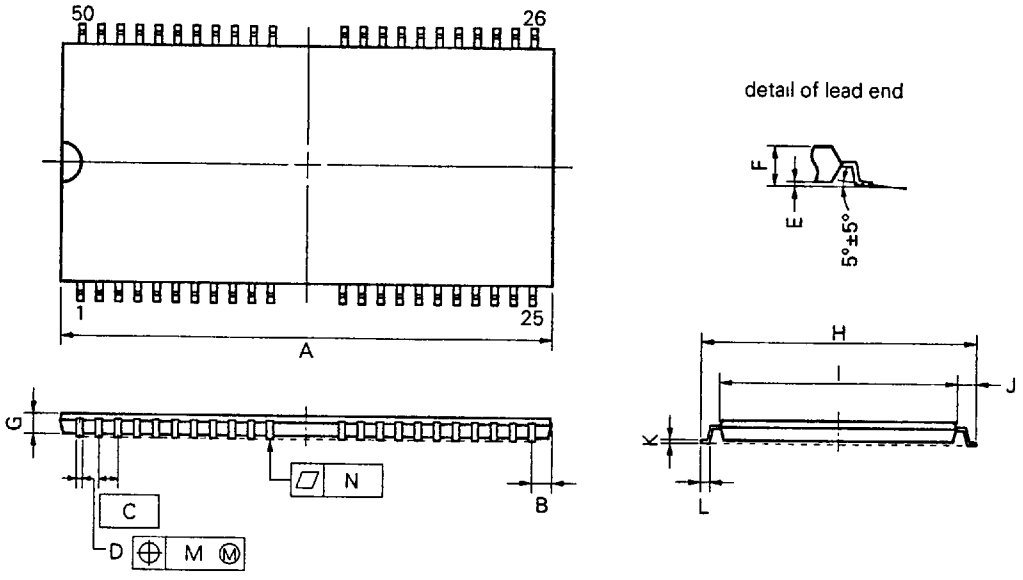
S32G5-50-7KD1

ITEM	MILLIMETERS	INCHES
A	21.17 MAX.	0.834 MAX.
B	1.06 MAX.	0.042 MAX.
C	1.27 (T.P.)	0.050 (T.P.)
D	0.40 ± 0.10	$0.016^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.15	$0.020^{+0.006}_{-0.007}$
M	0.21	0.009
N	0.10	0.004

50 PIN PLASTIC TSOP (400mil)

44 Leads

NEC Cord:S50G5-80-7JF



NOTE

Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

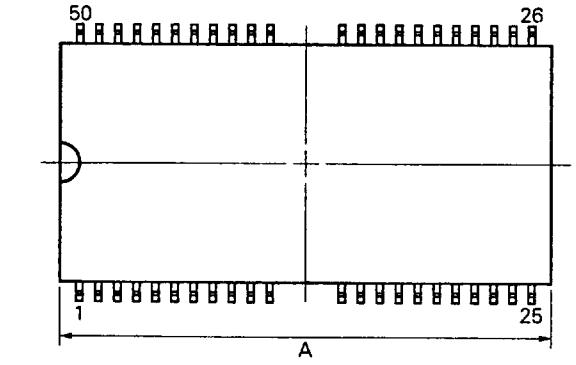
S50G5-80-7JF

ITEM	MILLIMETERS	INCHES
A	21.45 MAX.	0.845 MAX.
B	1.13 MAX.	0.045 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	0.30±0.10	$0.012^{+0.004}_{-0.005}$
E	0.05±0 05	0.002±0.002
F	1.1 MAX.	0.044 MAX.
G	0 97	0.038
H	11.76±0 2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5±0.15	$0.020^{+0.006}_{-0.007}$
M	0.13	0.005
N	0.10	0.004

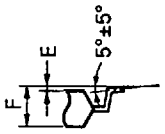
50 PIN PLASTIC TSOP (400mil)

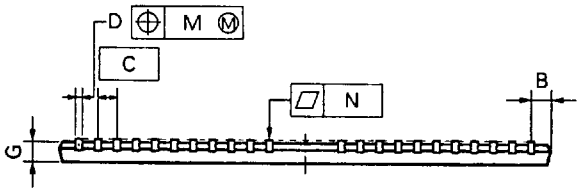
44 Leads Reverse bent

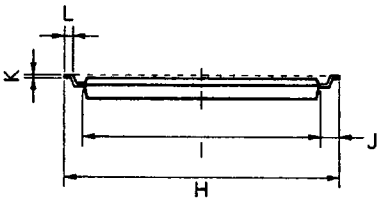
NEC Cord:S50G5-80-7KF



detail of lead end







NOTE

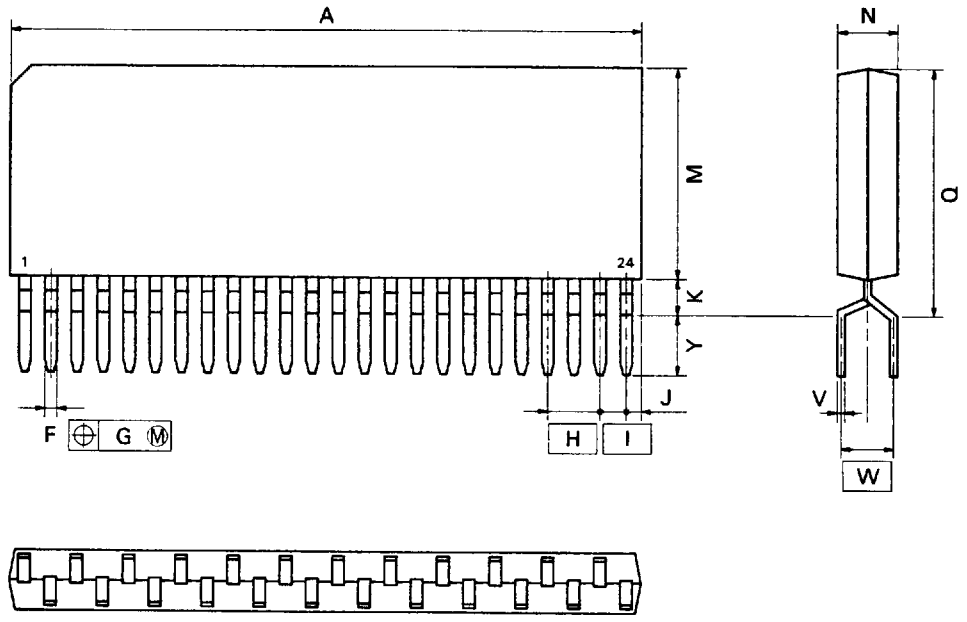
Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

S50G5-80-7KF

ITEM	MILLIMETERS	INCHES
A	21.45 MAX.	0.845 MAX.
B	1.13 MAX.	0.045 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	0.30 ± 0.10	$0.012^{+0.004}_{-0.005}$
E	0.05 ± 0.05	0.002 ± 0.002
F	1.1 MAX.	0.044 MAX.
G	0.97	0.038
H	11.76 ± 0.2	0.463 ± 0.008
I	10.16 ± 0.1	0.400 ± 0.004
J	0.8 ± 0.2	$0.031^{+0.009}_{-0.008}$
K	$0.125^{+0.10}_{-0.05}$	$0.005^{+0.004}_{-0.002}$
L	0.5 ± 0.15	$0.020^{+0.006}_{-0.007}$
M	0.13	0.005
N	0.10	0.004

24 PIN PLASTIC ZIP (475mil)

NEC Cord:P24V-100-475A



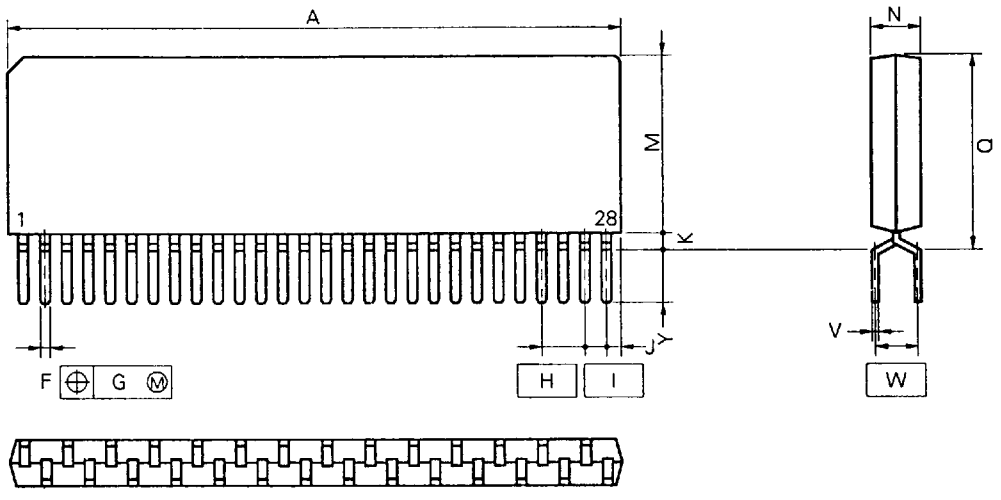
NOTE
Each lead centerline is located within 0.25 mm (0.010 inch) of its true position (T.P.) at maximum material condition.

P24V-100-475A

ITEM	MILLIMETERS	INCHES
A	31.75 MAX.	1.250 MAX.
F	$0.50^{\pm 0.1}$	$0.020^{+0.004}_{-0.005}$
G	ϕ0 25	ϕ0.010
H	2.54	0.100
I	1.27	0.050
J	1.27 MAX.	0.050 MAX.
K	1 0 MIN	0.039 MIN.
M	10 8 MAX	0 426 MAX
N	$2\ 8^{\pm 0.2}$	$0.110^{+0.009}_{-0.008}$
Q	12.07 MAX.	0.476 MAX
V	$0.25^{+0.10}_{-0.05}$	$0.010^{+0.004}_{-0.003}$
W	2.54	0.100
Y	$3.3^{+0.5}$	$0.130^{\pm 0.02}$

28 PIN PLASTIC ZIP (475mil)

NEC Cord:P28VF-100-475A



NOTE

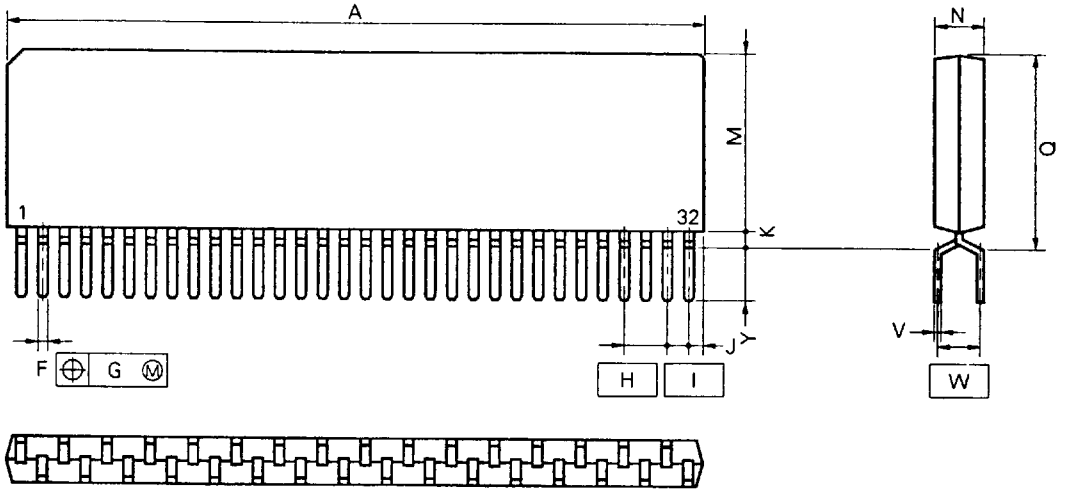
Each lead centerline is located within 0 25 mm (0.010 inch) of its true position (T.P) at maximum material condition.

P28VF-100-475A

ITEM	MILLIMETERS	INCHES
A	36.83 MAX.	1 450 MAX.
F	0 5±0 10	$0.020^{+0\ 004}_{-0\ 005}$
G	0.25	0.010
H	2 54 (T.P.)	0.100 (T P)
I	1 27 (T P.)	0.050 (T P.)
J	1 27 MAX.	0 050 MAX
K	0 9 MIN	0.035 MIN.
M	10 8 MAX.	0 426 MAX
N	2 8±0 2	$0.110^{+0\ 009}_{-0\ 008}$
Q	12 07 MAX	0 475 MAX.
V	$0\ 25^{+0\ 10}_{-0\ 05}$	$0.010^{+0\ 004}_{-0\ 003}$
W	2 54 (T.P.)	0.100 (T.P)
Y	3 25±0.2	0.128±0 008

32 PIN PLASTIC ZIP (475mil)

NEC Cord:P32VF-100-475A



NOTE

Each lead centerline is located within 0.25 mm (0.010 inch) of its true position (T.P.) at maximum material condition.

P32VF-100-475A

ITEM	MILLIMETERS	INCHES
A	41.91 MAX.	1.650 MAX
F	0.5±0.10	$0.020^{+0.004}_{-0.005}$
G	0.25	0.010
H	2.54 (T.P.)	0.100 (T.P.)
I	1 27 (T.P)	0.050 (T.P.)
J	1.27 MAX.	0.050 MAX.
K	0 9 MIN.	0.035 MIN.
M	10.8 MAX.	0.426 MAX.
N	2 8±0.2	$0.110^{+0.009}_{-0.008}$
Q	12.07 MAX.	0.475 MAX.
V	$0.25^{+0.10}_{-0.05}$	$0.010^{+0.004}_{-0.003}$
W	2.54 (T.P.)	0 100 (T P.)
Y	3.25±0.2	0.128±0.008